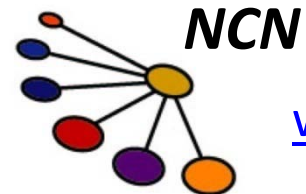


2009 NCN@Purdue-Intel Summer School
Notes on Percolation and Reliability Theory

Lecture 8

On the Mechanics of Defect Generation and Gate Dielectric Breakdown

Muhammad A. Alam
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West Lafayette, IN USA



NCN

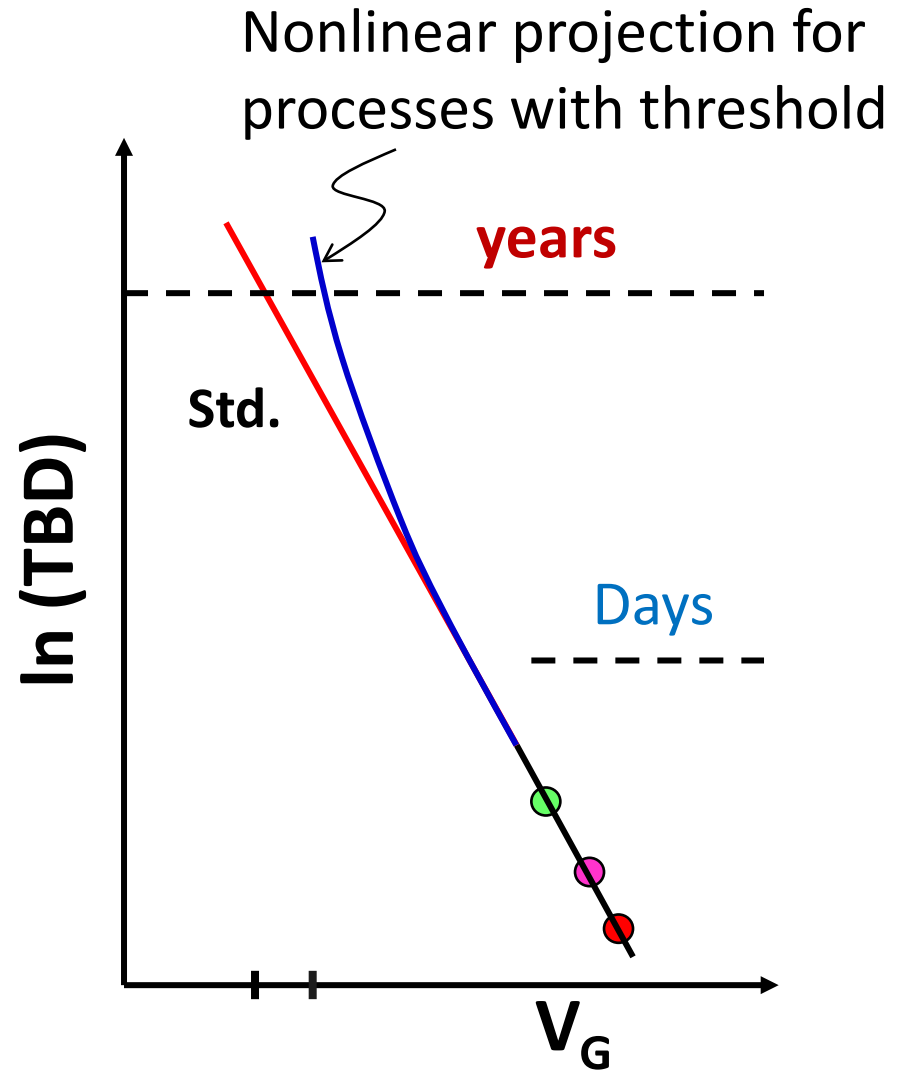
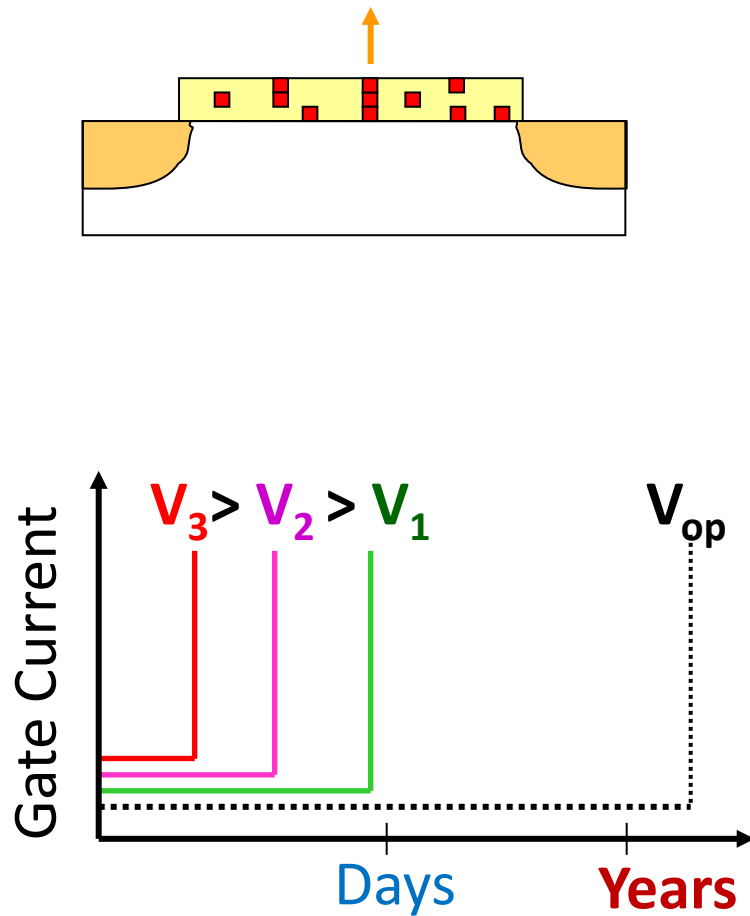
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outline of lecture 8

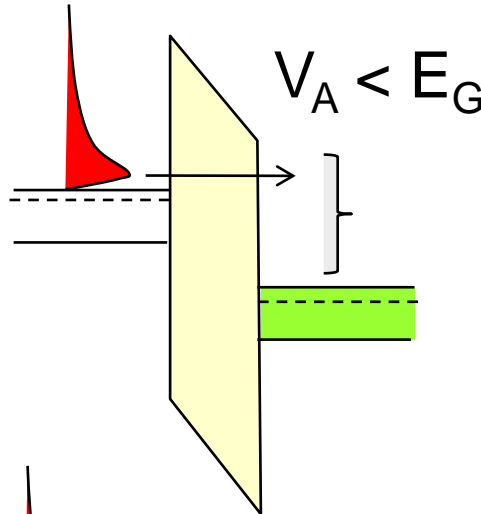
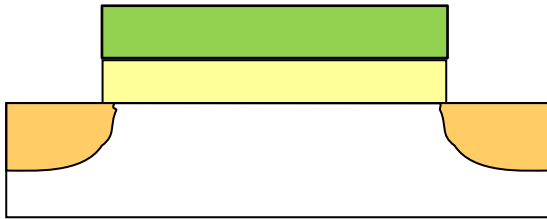
- 1) Theory of oxide breakdown**
- 2) Statistics of Failure Distribution
- 3) Soft vs. Hard Breakdown
- 4) Correlated vs. Uncorrelated Breakdown
- 5) Conclusions

how to determine gate oxide reliability

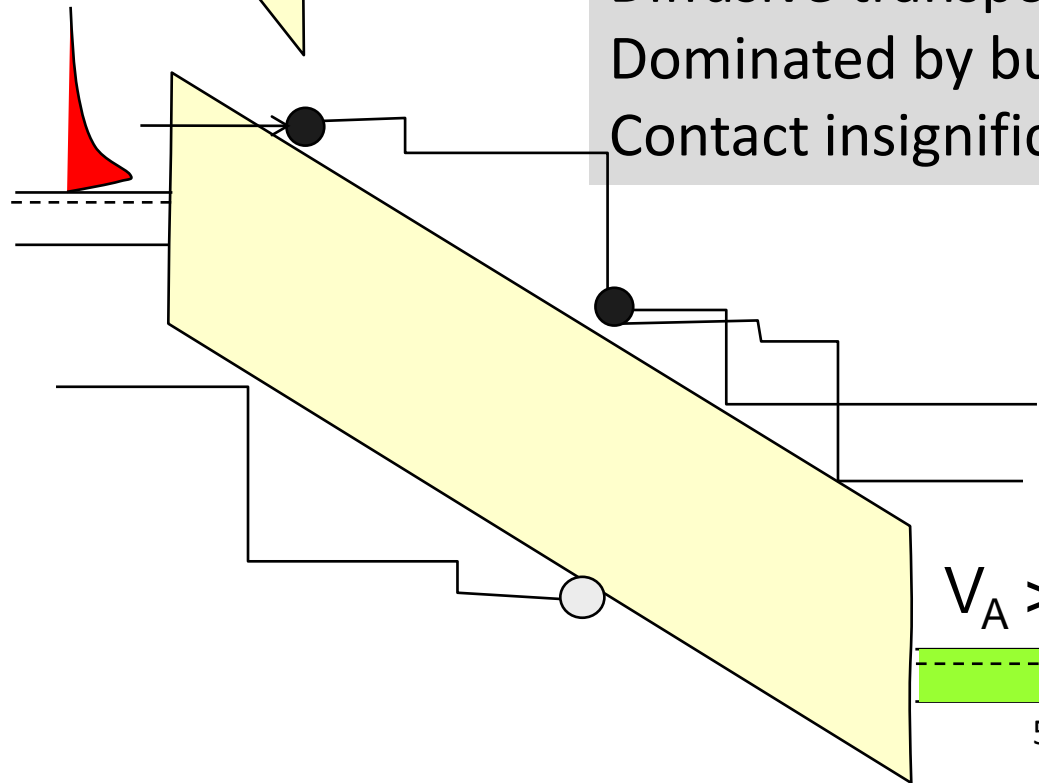
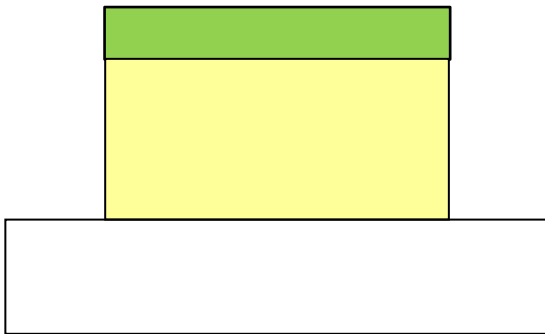


Empirical projection is very difficult, if not impossible ...

breakdown in thick vs. thin oxides



Ballistic transport
Hot contact
Contact dictates BD



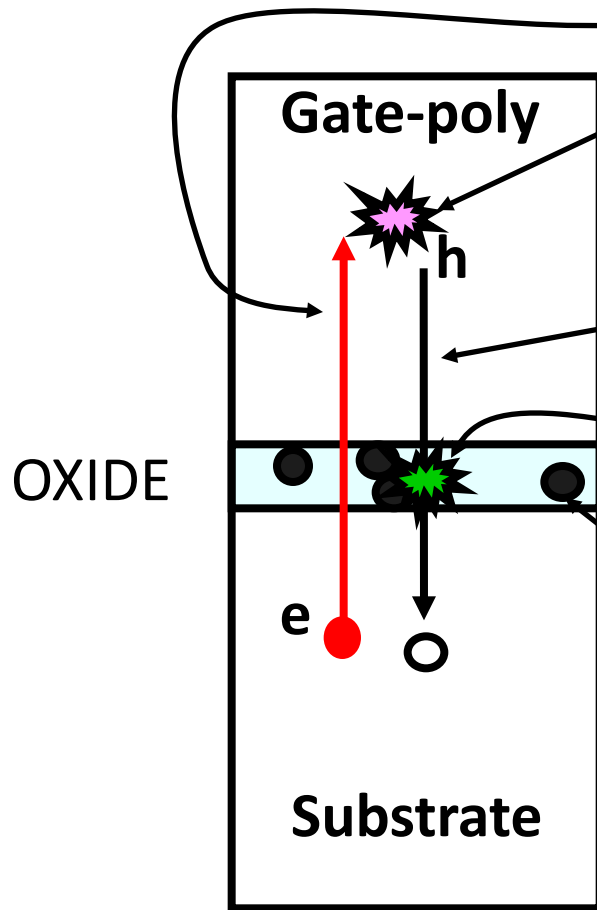
Diffusive transport
Dominated by bulk
Contact insignificant

$$\frac{dE}{dx} = q\mathcal{E}_{ox} - \frac{E}{\lambda}$$

$$V_A \gg E_G$$

theory of anode hole injection

$$T_{BD} = \left(\frac{N_{BD}}{k} \right)^n \frac{1}{J_e \alpha T_p}$$



J_e - Electron current density

α - Impact Ionization Rate
(probability that a hole will be created by an incoming electron)

T_p - Transmission Rate
(probability that the hole will travel through the oxide layer)

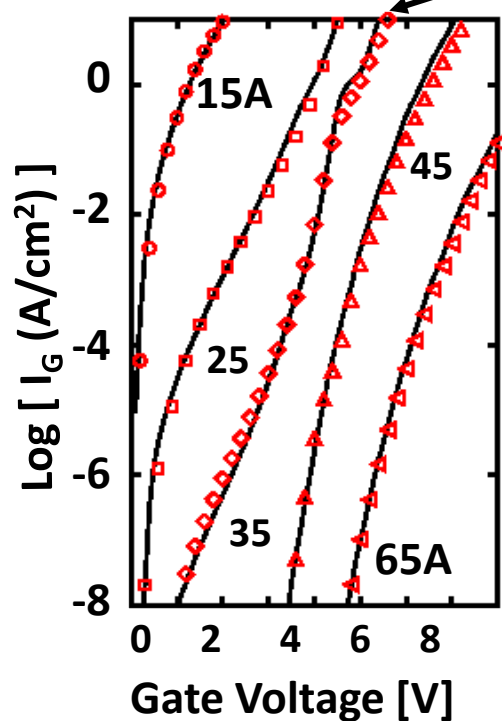
k - Trap Generation Efficiency
(probability that the hole will create a percolation defect)

N_{BD} - Density of percolation defects at breakdown

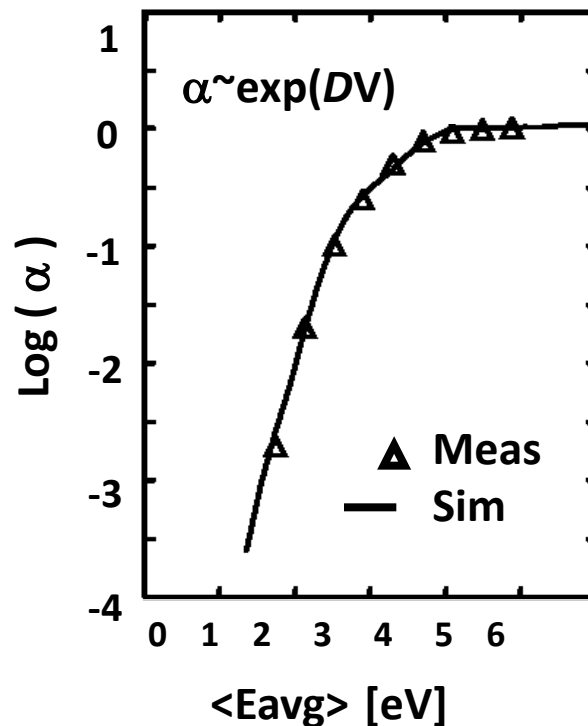
Ballistic transport and hot contacts ... in 1980s!

AHI model: numerical calculation

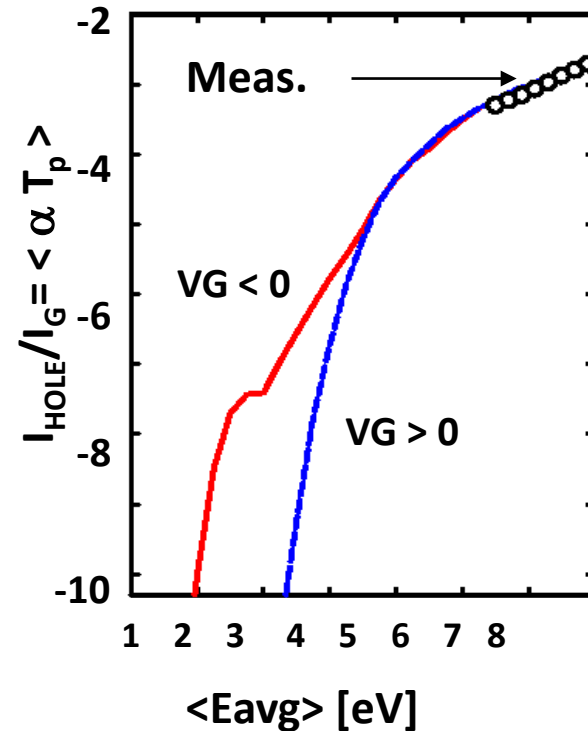
$$J_h = J_e \alpha T_p$$



Ghetti, INFOS99
Lo, APL97

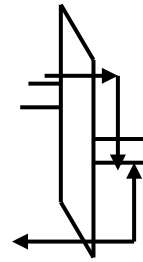


Bude (IEDM98)
Ezaki (SISC00)
Kamakura (IEDM99, JAP00)
Palestri (SISC00)

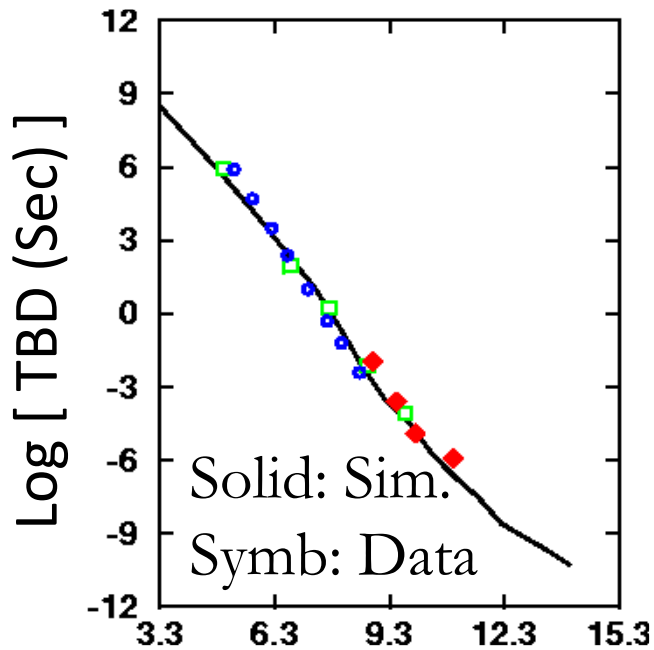


Bude (IEDM98)
Alam (IRPS00)
Palestri (SISC00)

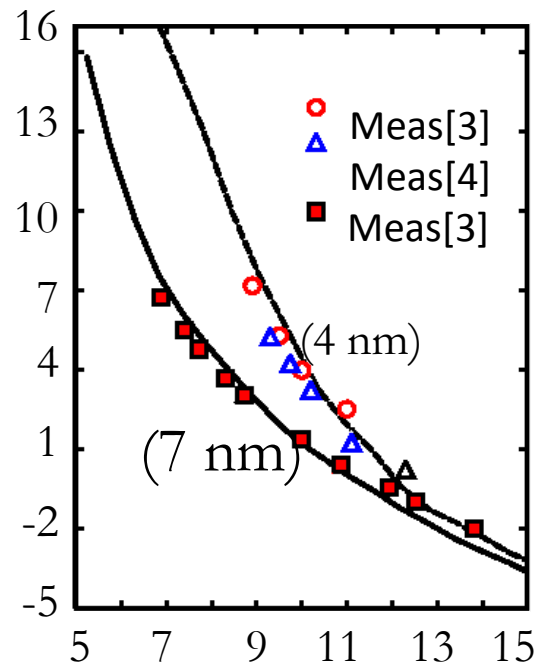
AHI model verified



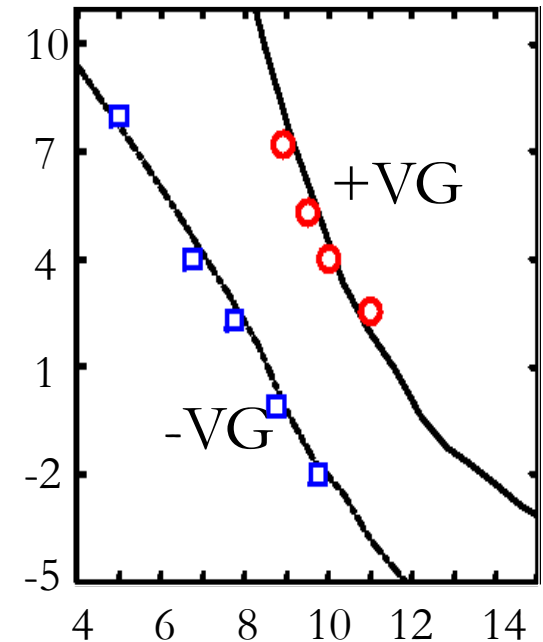
Field Dependence



Tox Dependence.



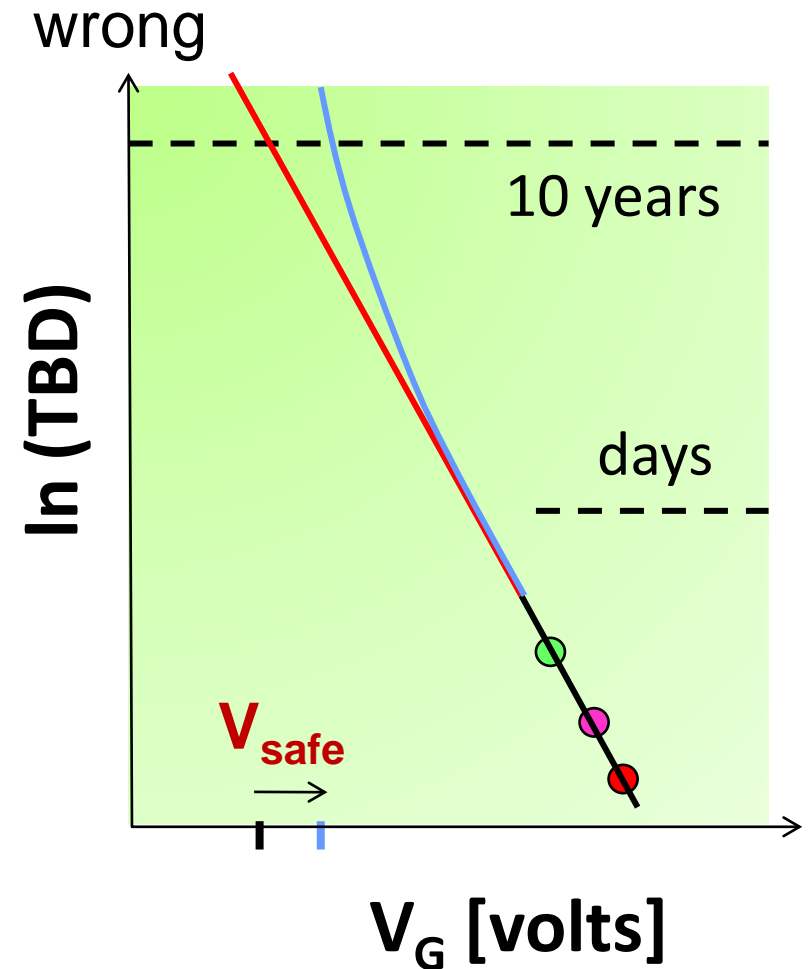
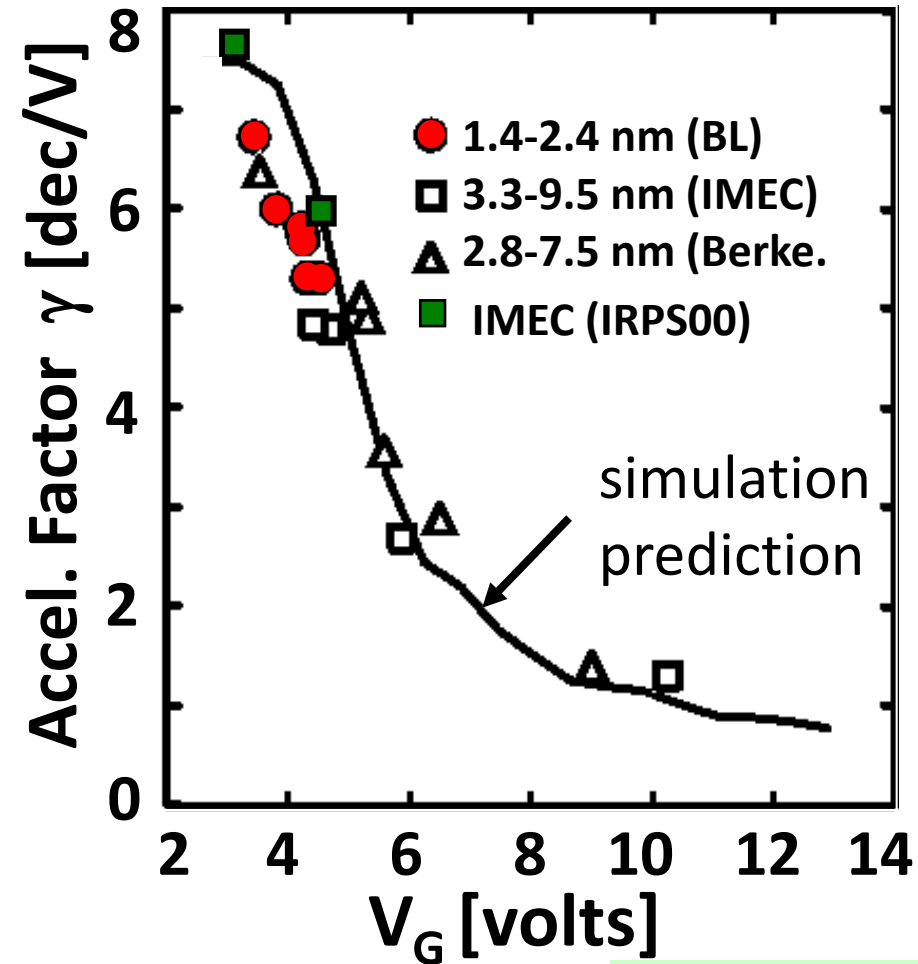
Polarity Dependence



Electric Field (MV/cm)

[1] Teramoto, IRPS, 99, [2] Yassine, APL, 99. [3] T. Nigam, JAP, 97

reduced defect generation at low voltage

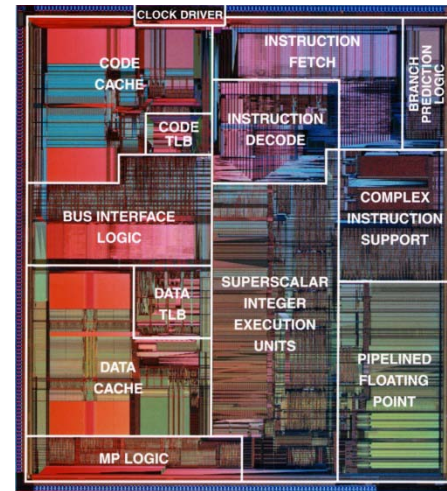


$$V_{safe} = V_{test} - \log \left[\frac{10 \text{ yr}}{T_{BD,Test}} \right] / \gamma$$

.... but this is a statistical problem

1 CPU $\sim 10^8 - 10^9$ Transistors

When one transistor fails, so does the IC

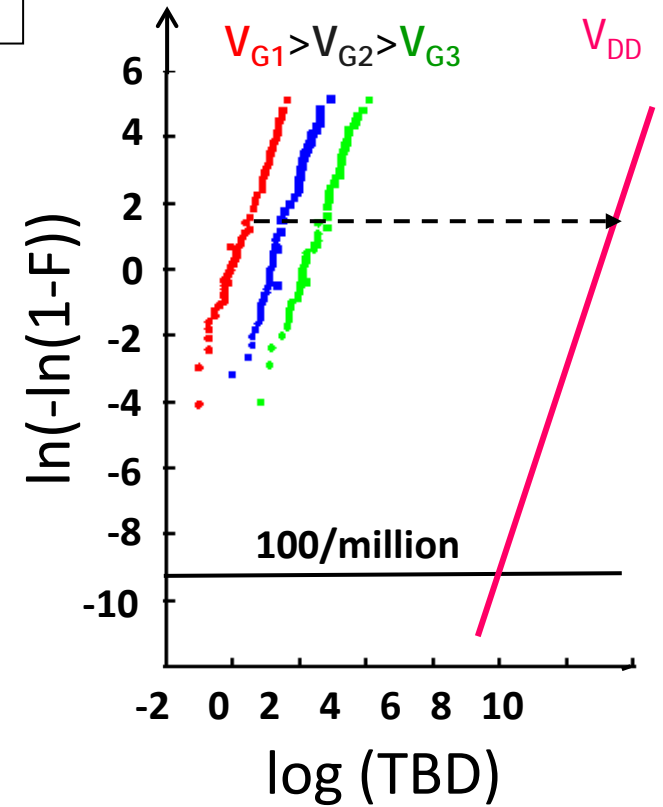
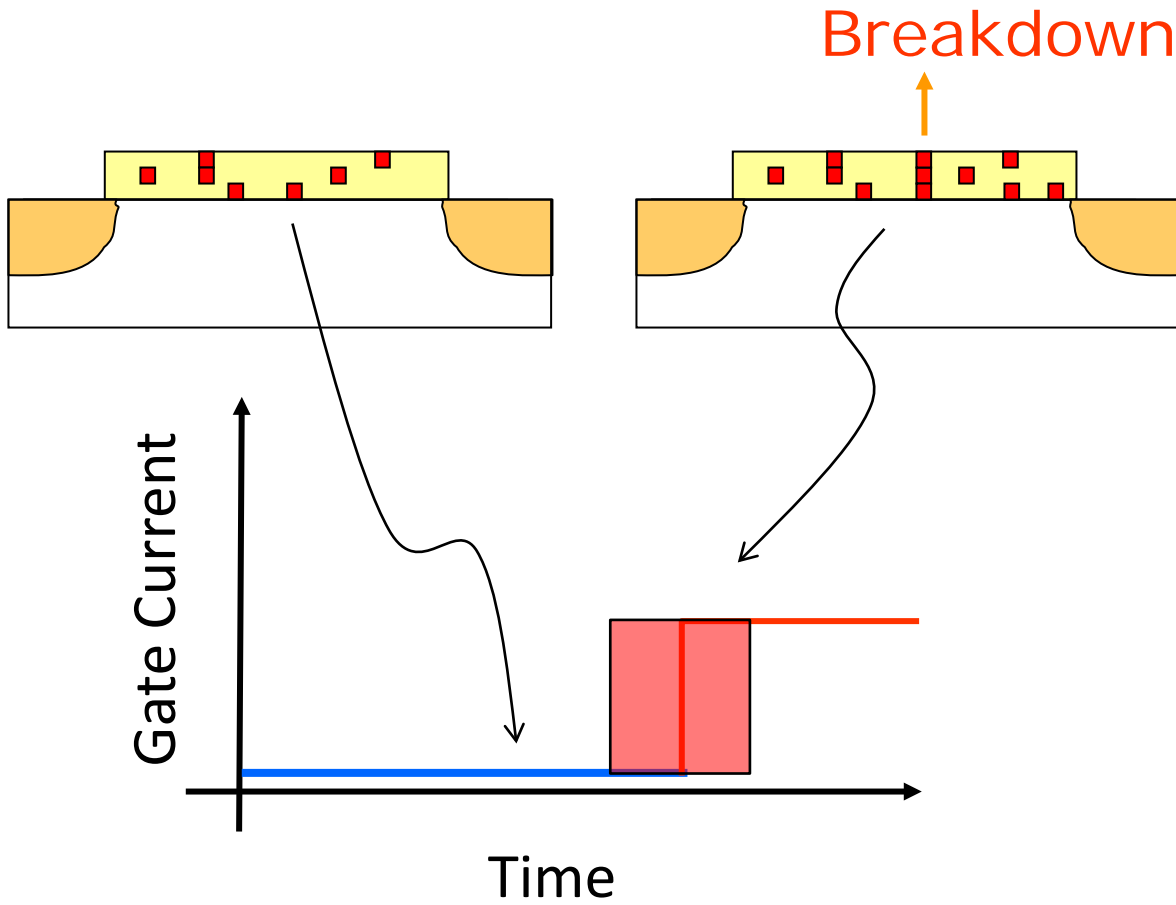


Statistics connects reliability and variability in a fundamental way ...

outline of lecture 8

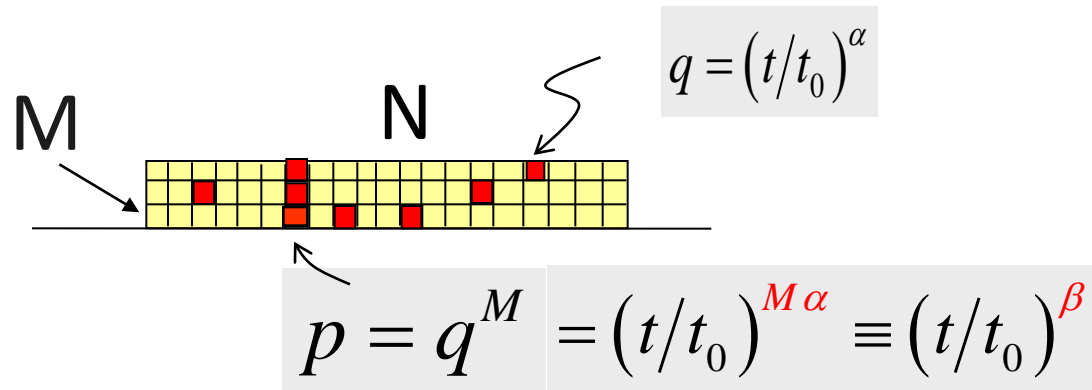
- 1) Theory of oxide breakdown
- 2) Statistics of Failure Distribution**
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- 5) Conclusions

mean failure time vs. failure time distribution



Average lifetime is not good enough

(simple) theory of statistical breakdown



$$P_0 = (1 - p)^N = (1 - Np/N)^N = \exp(-Np)$$

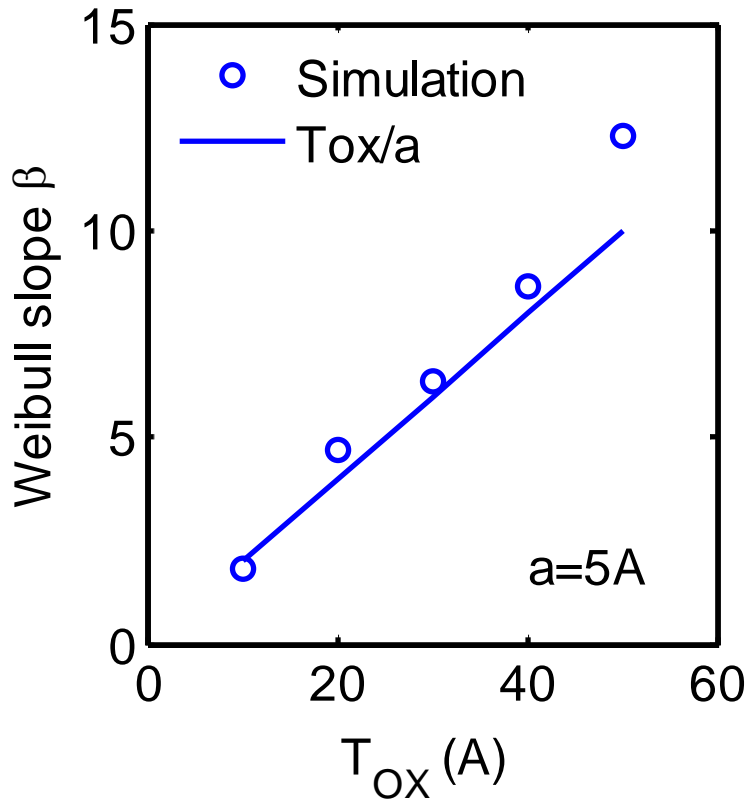
$$1 - F(p) = P_0 = \exp(-Np)$$

$$W \equiv \ln(-\ln(1 - F)) = \beta \ln(t) - M\alpha \ln(t_0) + \ln(N)$$

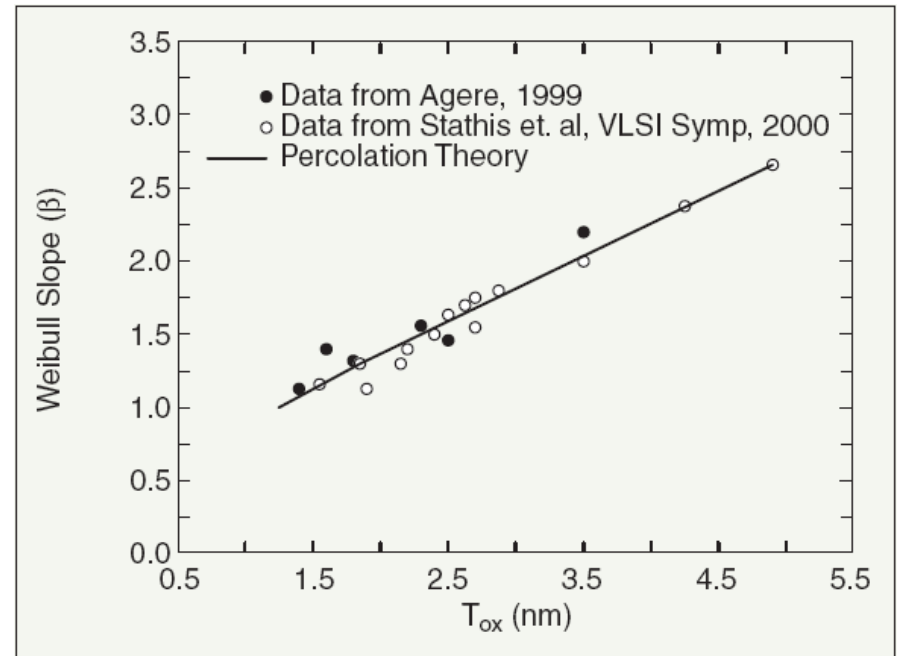
Straight-line in a Weibull plot, slope proportional to thickness

bottom-up prediction for oxide scaling

Theory



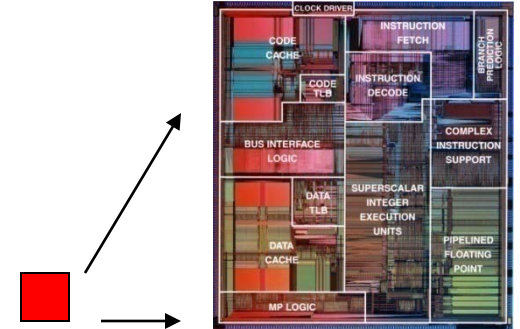
Measurement



Thin oxide breaks much faster than thick oxide due to percolation, process-improvement cannot solve this problem

lifetime projection ...

$$T_{BD}^{50\%}(A_{IC}) = (A_{TEST} / A_{IC})^{1/\beta} T_{BD}^{50\%}(A_{TEST})$$

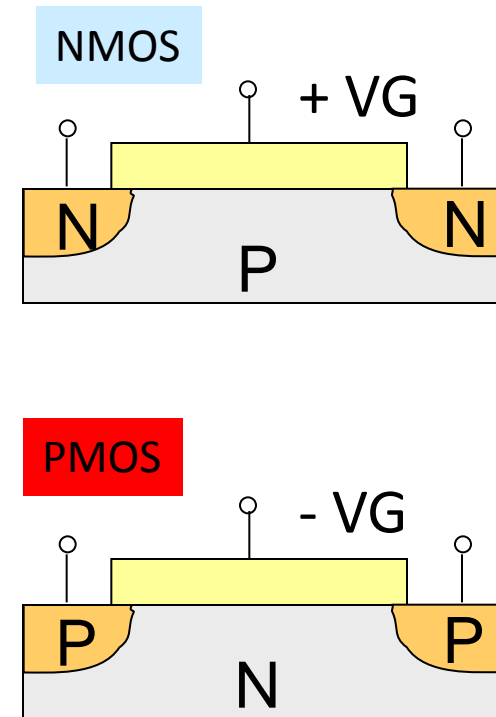
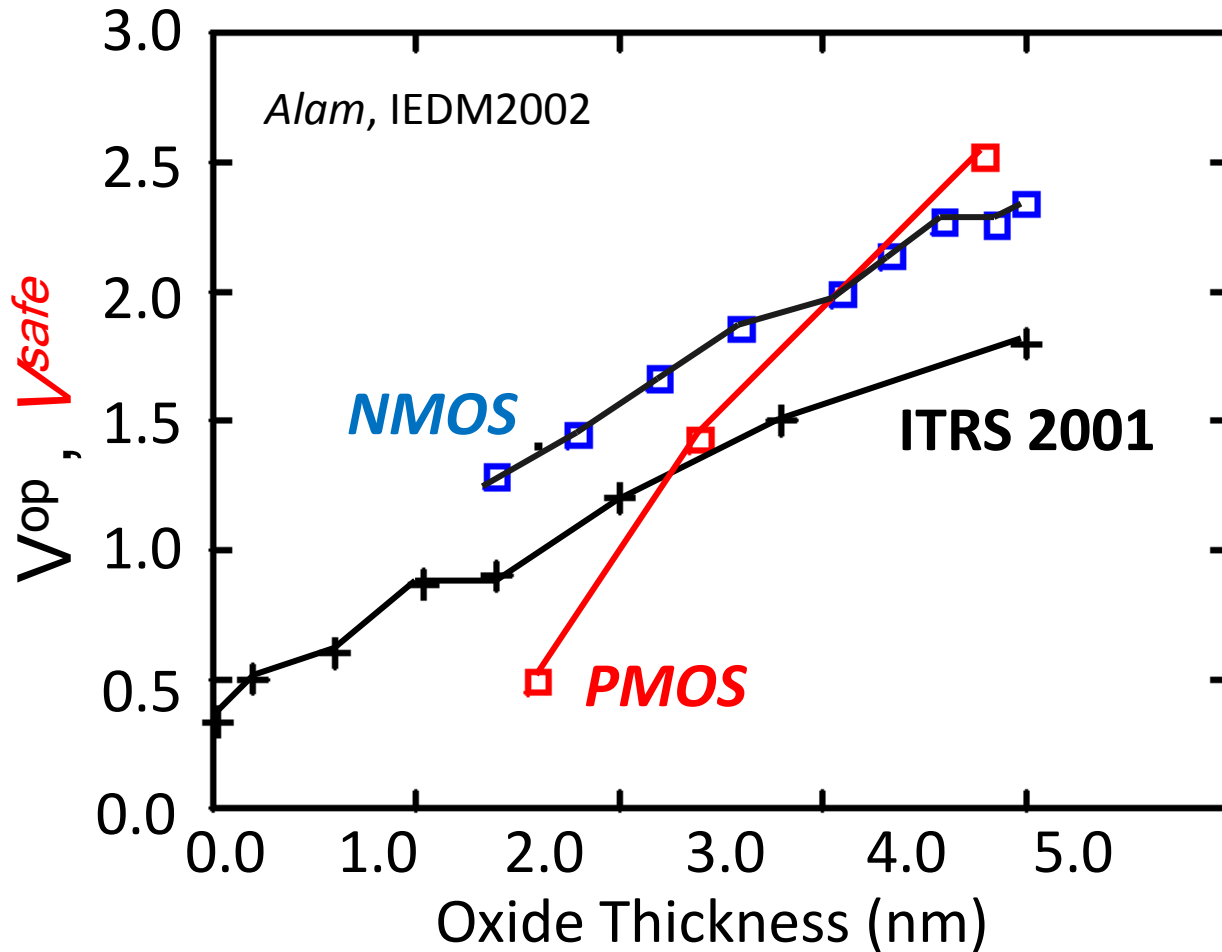


$$T_{BD}^{q\%}(A_{IC}) = \left[\frac{\ln(1 - q / 100)}{\ln(1 - 0.5)} \right]^{1/b} T_{BD}^{50\%}(A_{IC})$$

$$V_{safe} = V_{test} - \log \left[\frac{10 \text{ yrs}}{T_{BD}^{q\%}} \right] / Y_{V,acc}$$

HW: Derive this equations based on the last 5 slides

NMOS vs. PMOS reliability

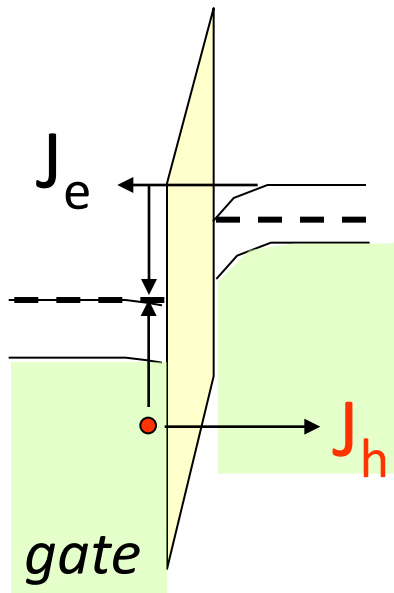


PMOS less reliable than NMOS, contacts defines everything !

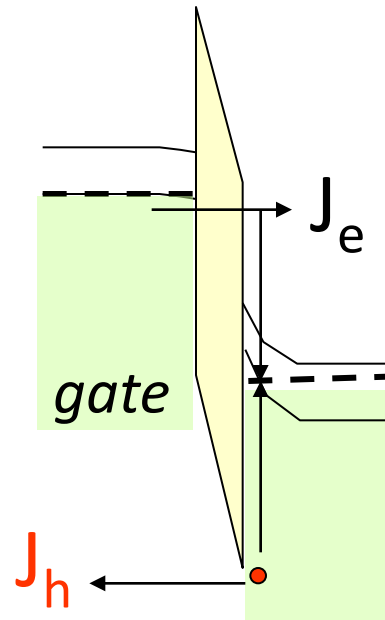
PMOS less reliable than NMOS below 2 nm

$$T_{BD} \sim 1/J_h \text{ with } J_h = J_e \langle \alpha T_h \rangle$$

NMOS



PMOS



For oxide < 2 nm:

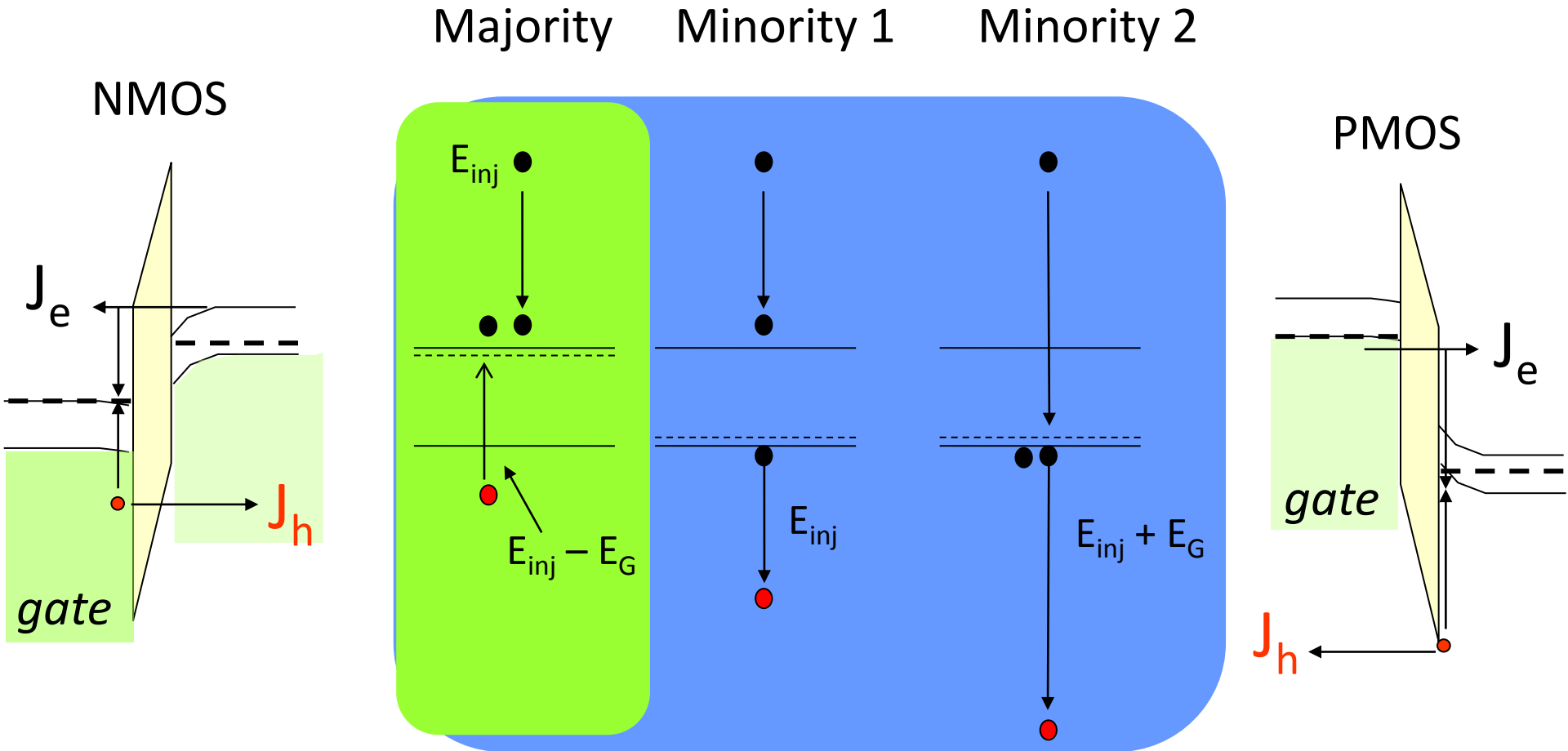
$$J_h^{\text{PMOS}} > J_h^{\text{NMOS}}, \text{ so}$$

$$T_{BD}^{\text{PMOS}} < T_{BD}^{\text{NMOS}}$$

Bude, IEDM98
Alam, IRPS00
Weir, ECS02

majority vs. minority ionization ...

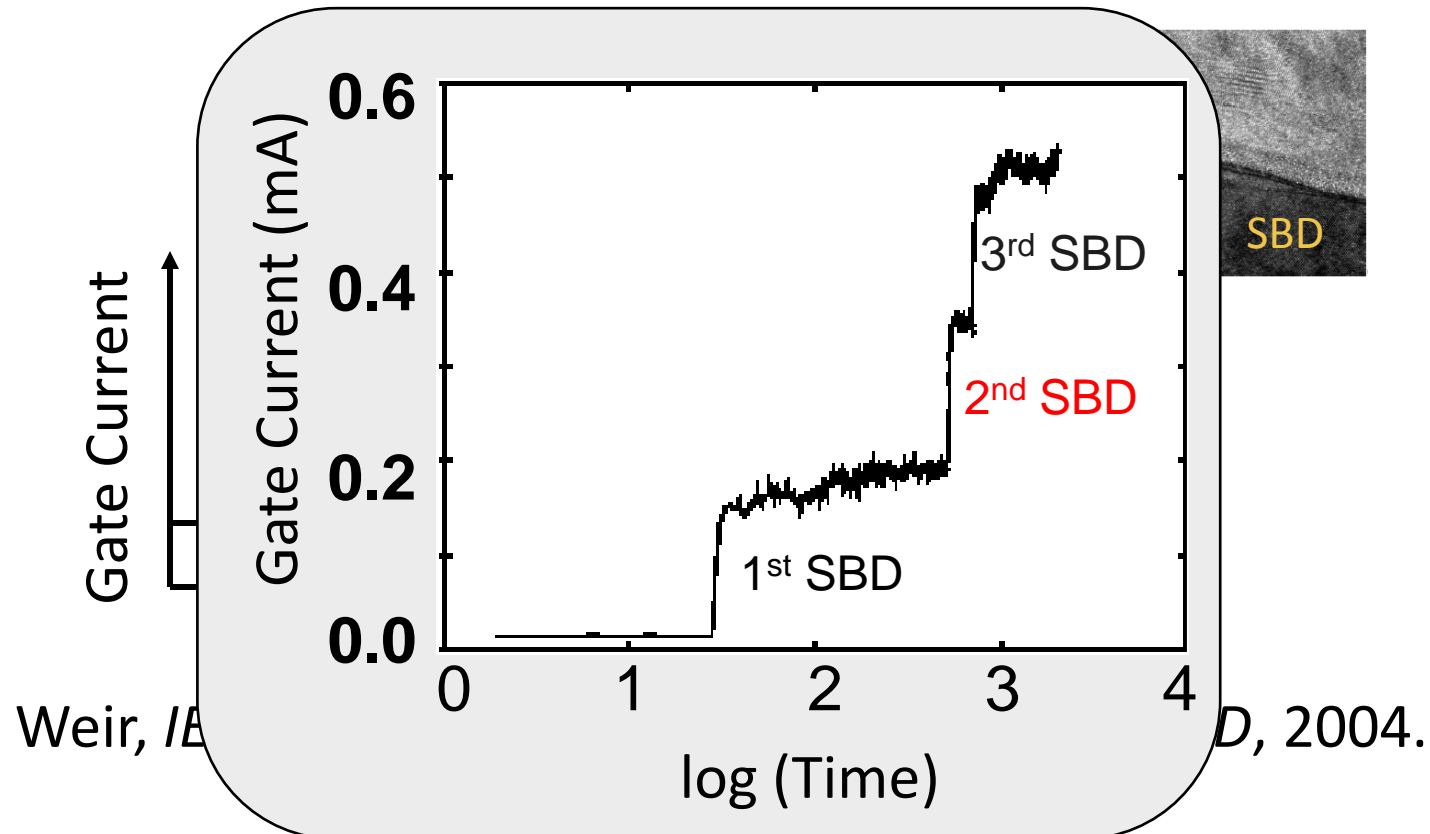
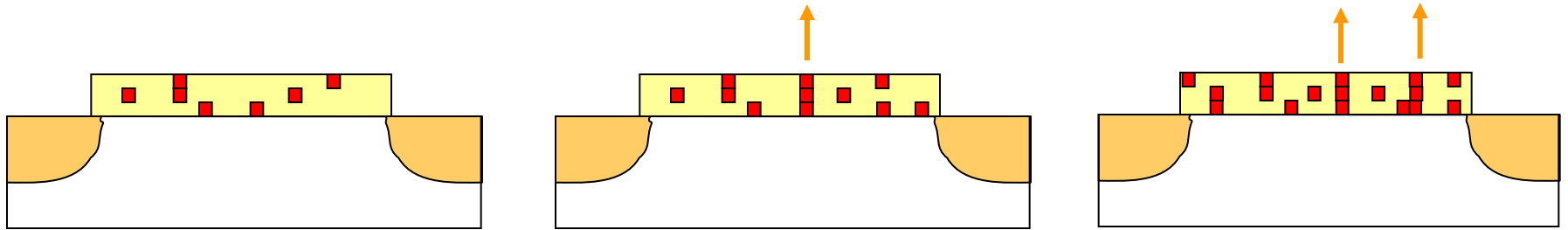
role of **hot** contacts



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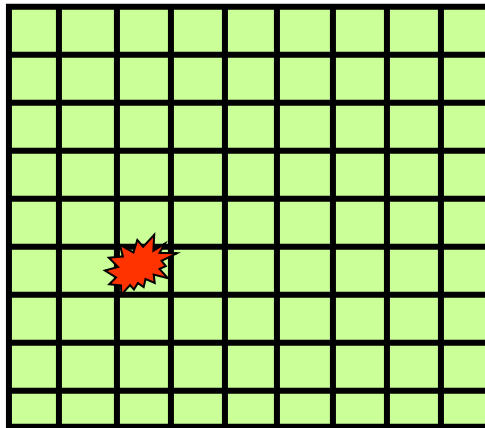
- 1) Theory of oxide breakdown
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soft breakdown for PMOS

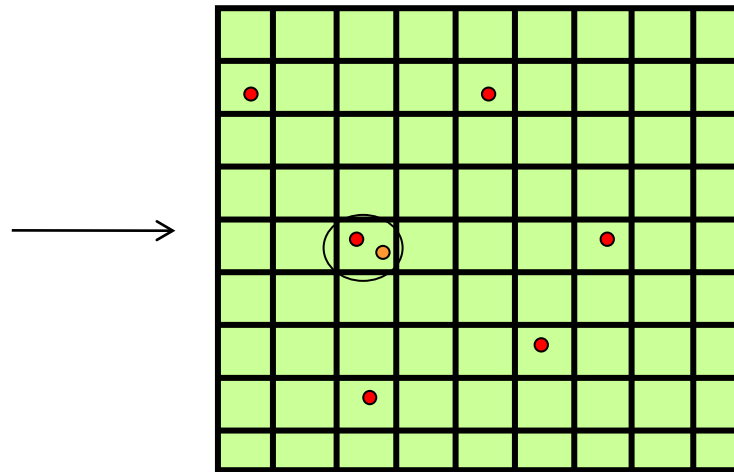


physical reasons for improved reliability

Standard reliability

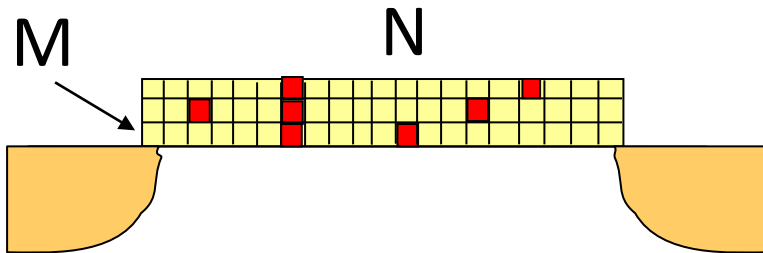


reliability with soft breakdown



Many BD in IC before 2nd BD in the same transistor

statistics of soft breakdown



Prob. of a filled column: $p = q^M$

Prob. of filled cell: $q = (at^\alpha / NM)$

Prob. of exactly n-SBD

$$P_n = {}^N C_n [p^n] [(1-p)^{(N-n)}]$$

$$P_n = (\chi^n / n!) \exp(-\chi)$$

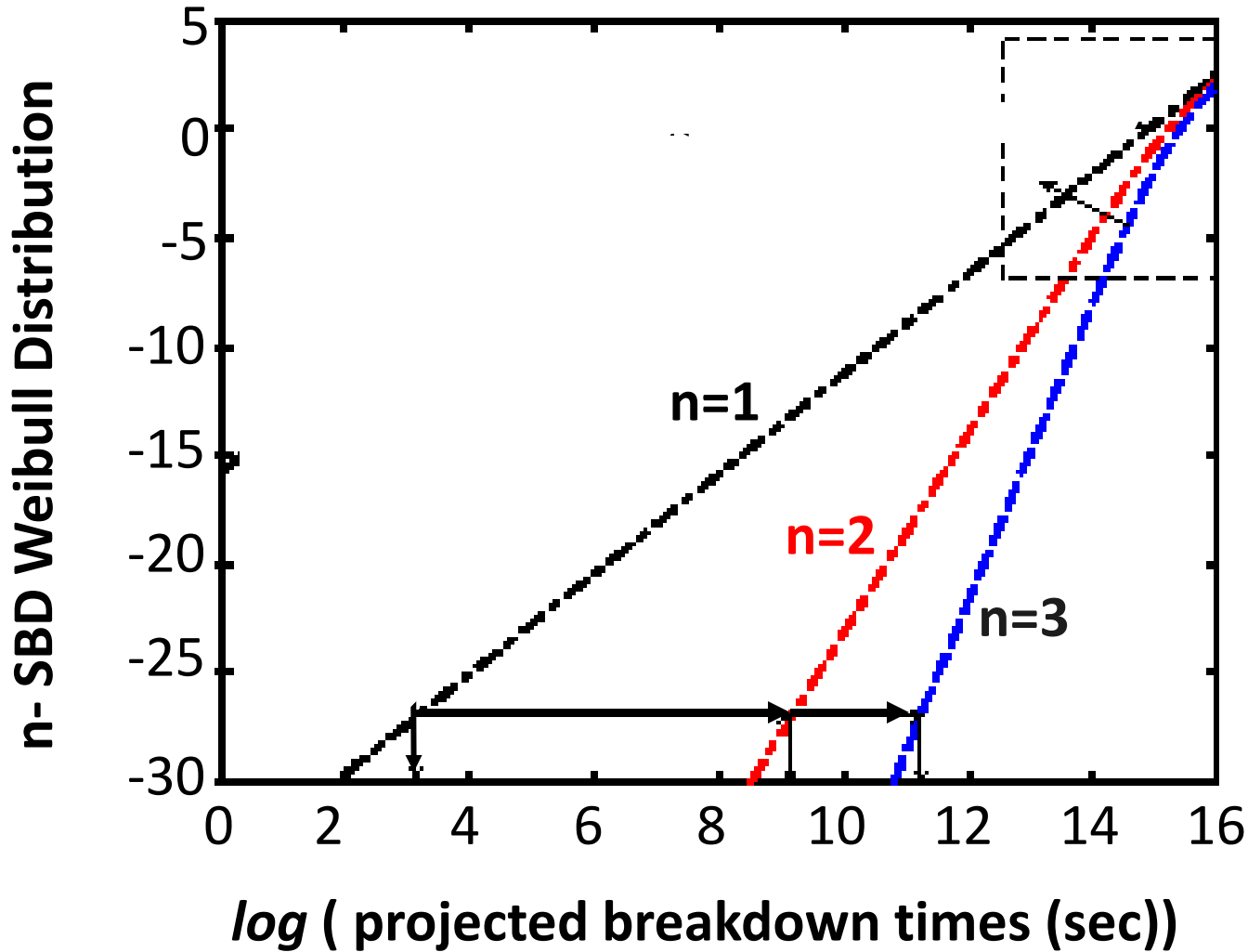
with $\chi = (t/\eta)^\beta$ and $\beta = M\alpha$

Prob. of $\geq n$ SBD

$$F_n(\chi) = 1 - \sum_{k=0}^{n-1} P_k(\chi)$$

Measured data: $W_n = \ln [-\ln (1-F_n)]$

lifetime improvement

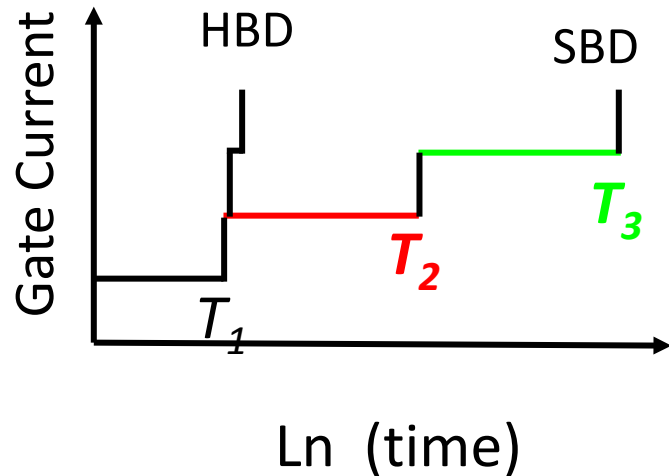


100 million
Transistors

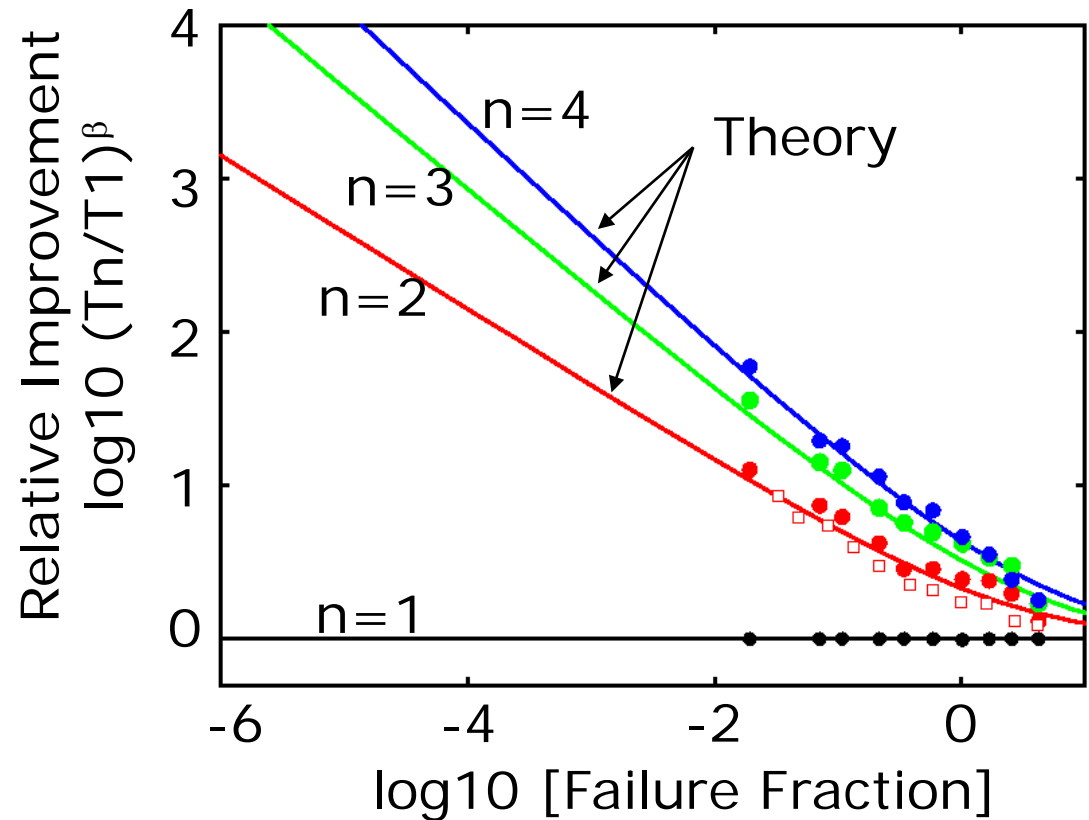
1 part per
 10^4 failure

SBD improves lifetime geometrically ...

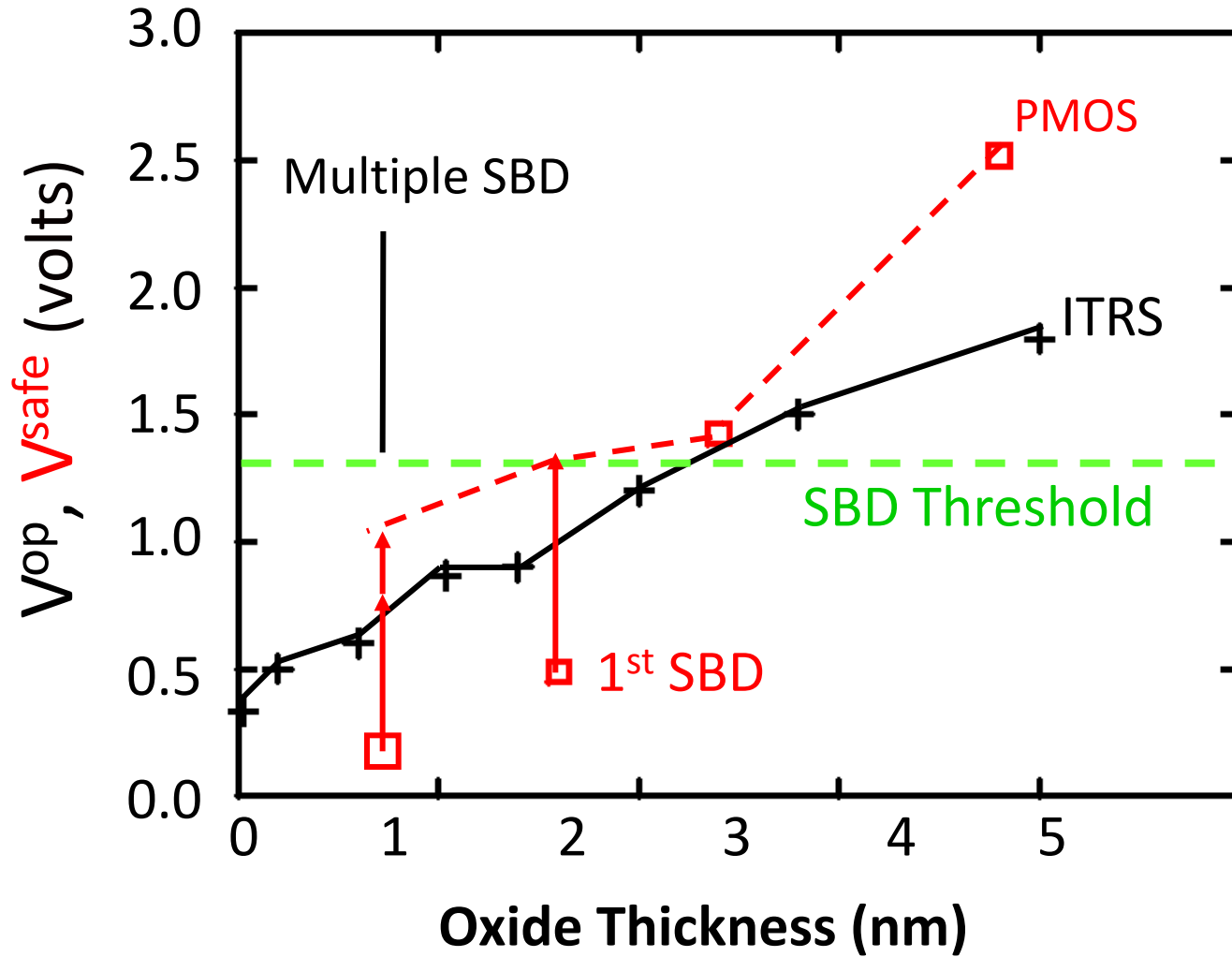
$$(T_n/T_1)^\beta = (n/e)(2\pi n)^{1/2n} / F_n^{(1-1/n)}$$



Alam, Nature, 2003



PMOS reliability with SBD

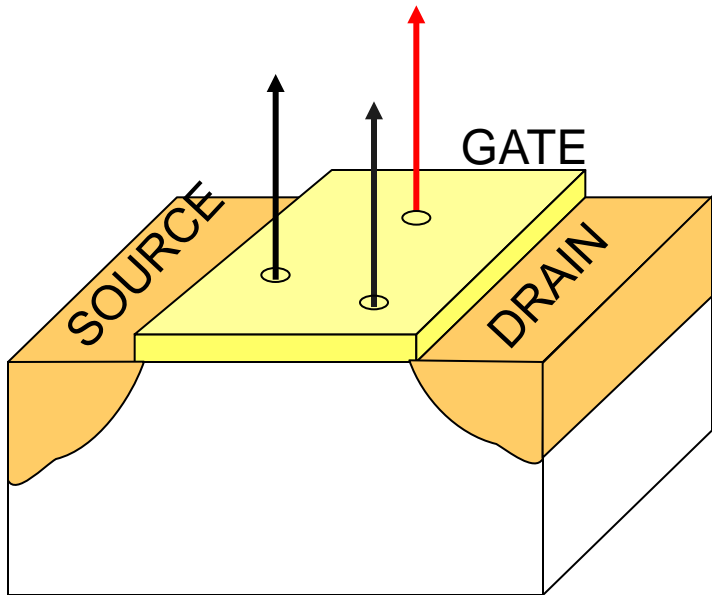


outline of lecture 8

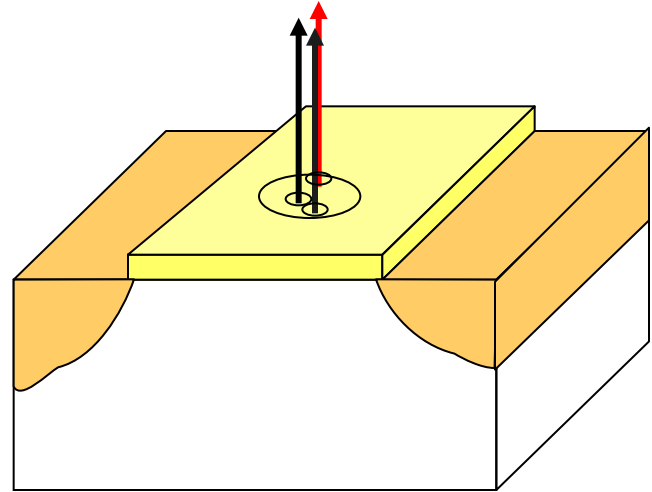
- 1) Theory of oxide breakdown
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partially correlated breakdown

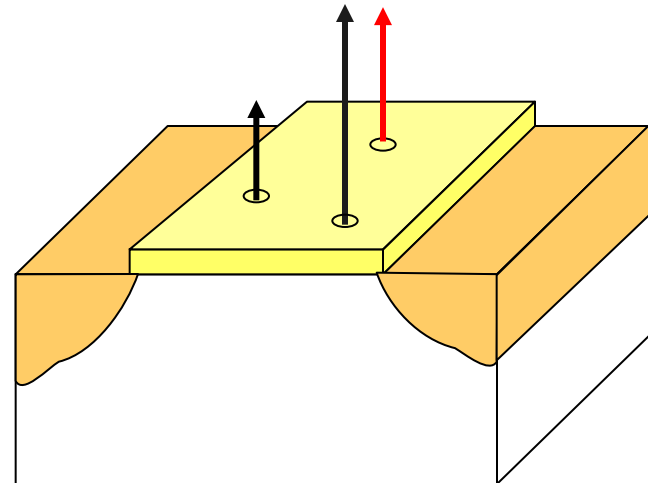
Spatially and Temporally
uncorrelated



Spatially correlated

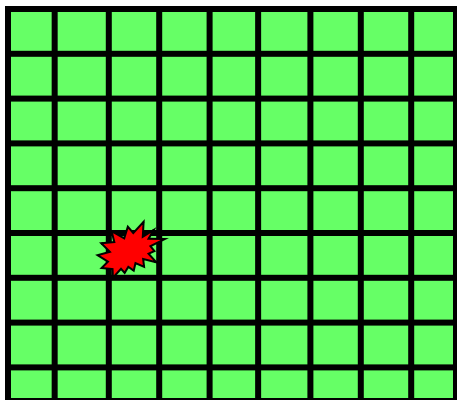


Temporally correlated

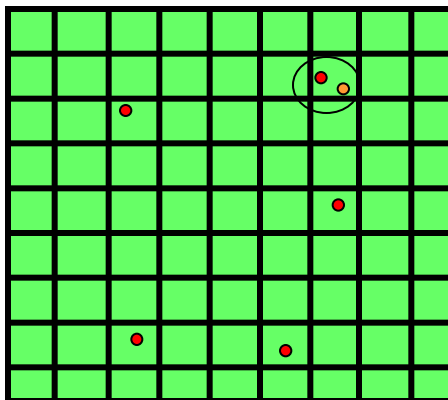


soft BD improves dielectric lifetime

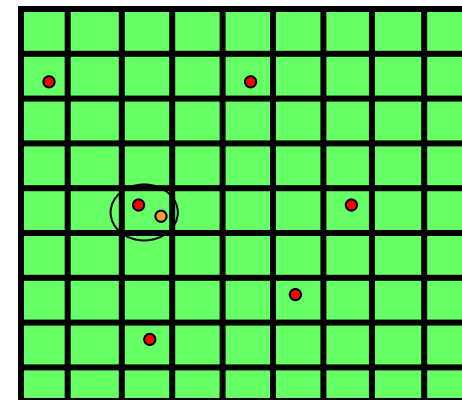
Std. definition



Measurement



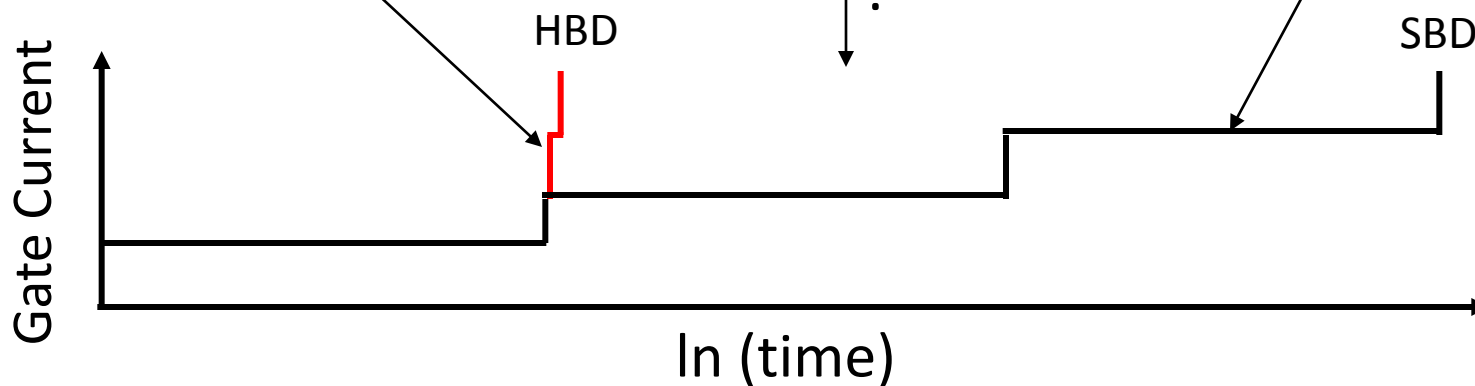
Theory



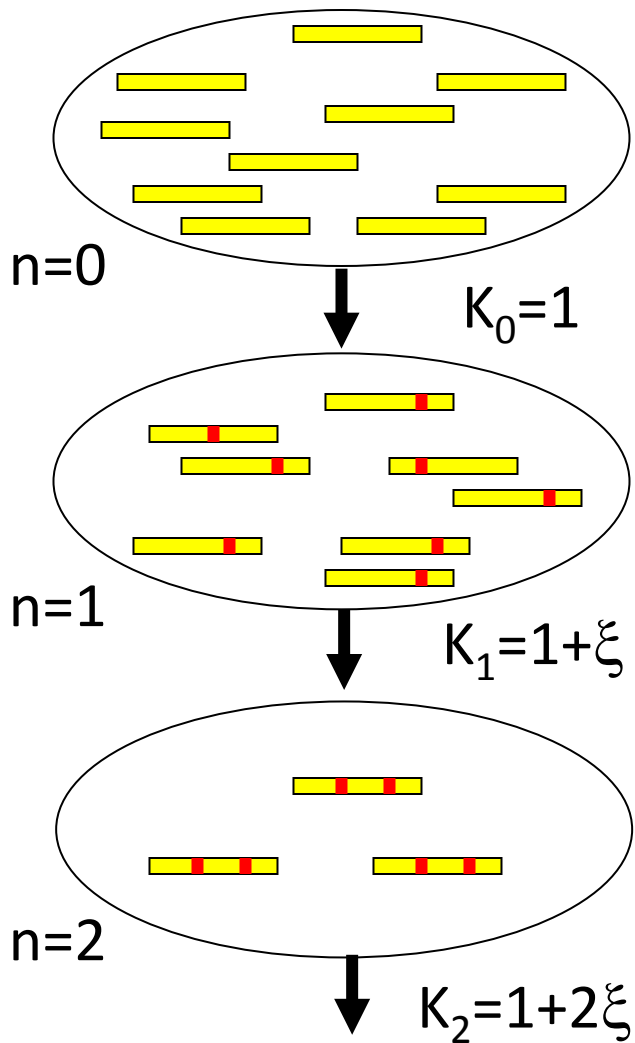
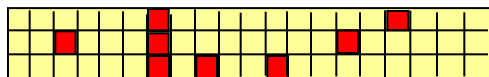
Completely correlated

“Essentially” uncorrelated

Completely uncorrelated



computing number of devices with n-SBD



$$\frac{dP_o}{d\chi} = -k_o P_o$$

$$\chi = (t/\eta)^\beta$$

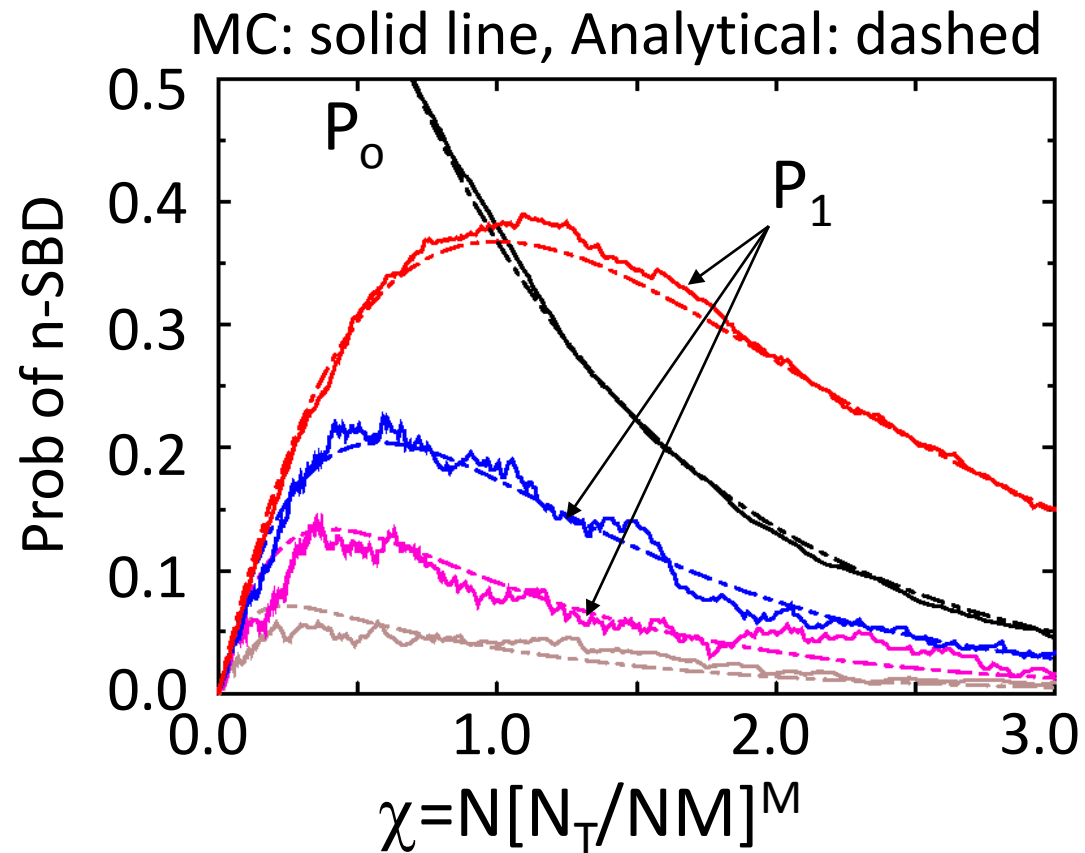
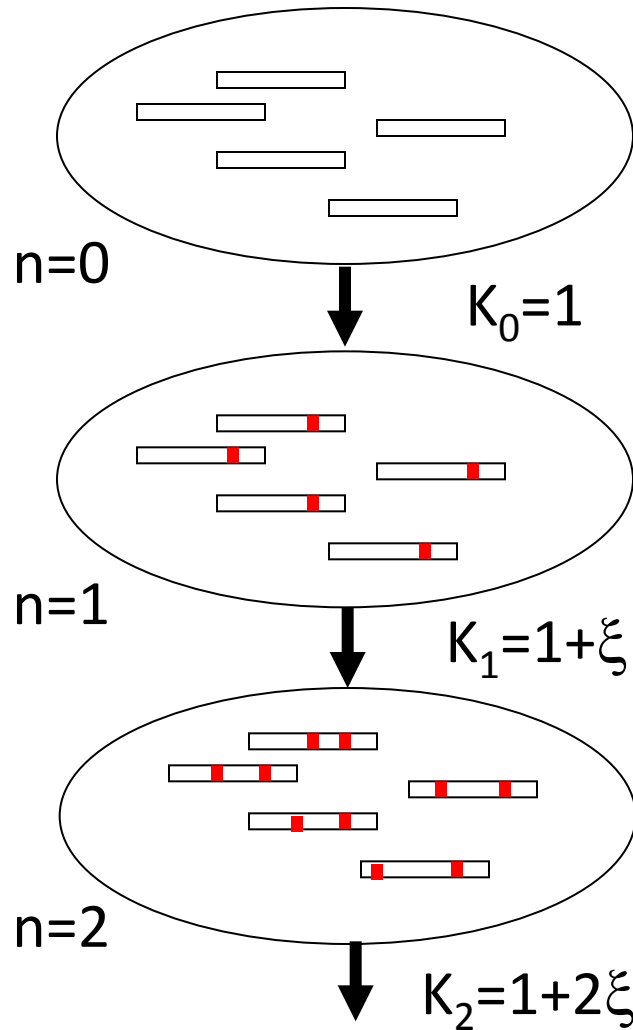
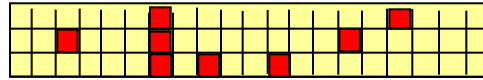
$$\frac{dP_n}{d\chi} = k_{n-1} P_{n-1} - k_n P_n$$

$$P_o = \exp(-\chi)$$

$$P_n = f(\xi) (\chi^n / n!) \exp(-\chi)$$

$$f(\xi) = \prod_{m=0}^{n-1} (1 + m\xi) [1 - \exp(-\xi\chi)] / \xi\chi^n$$

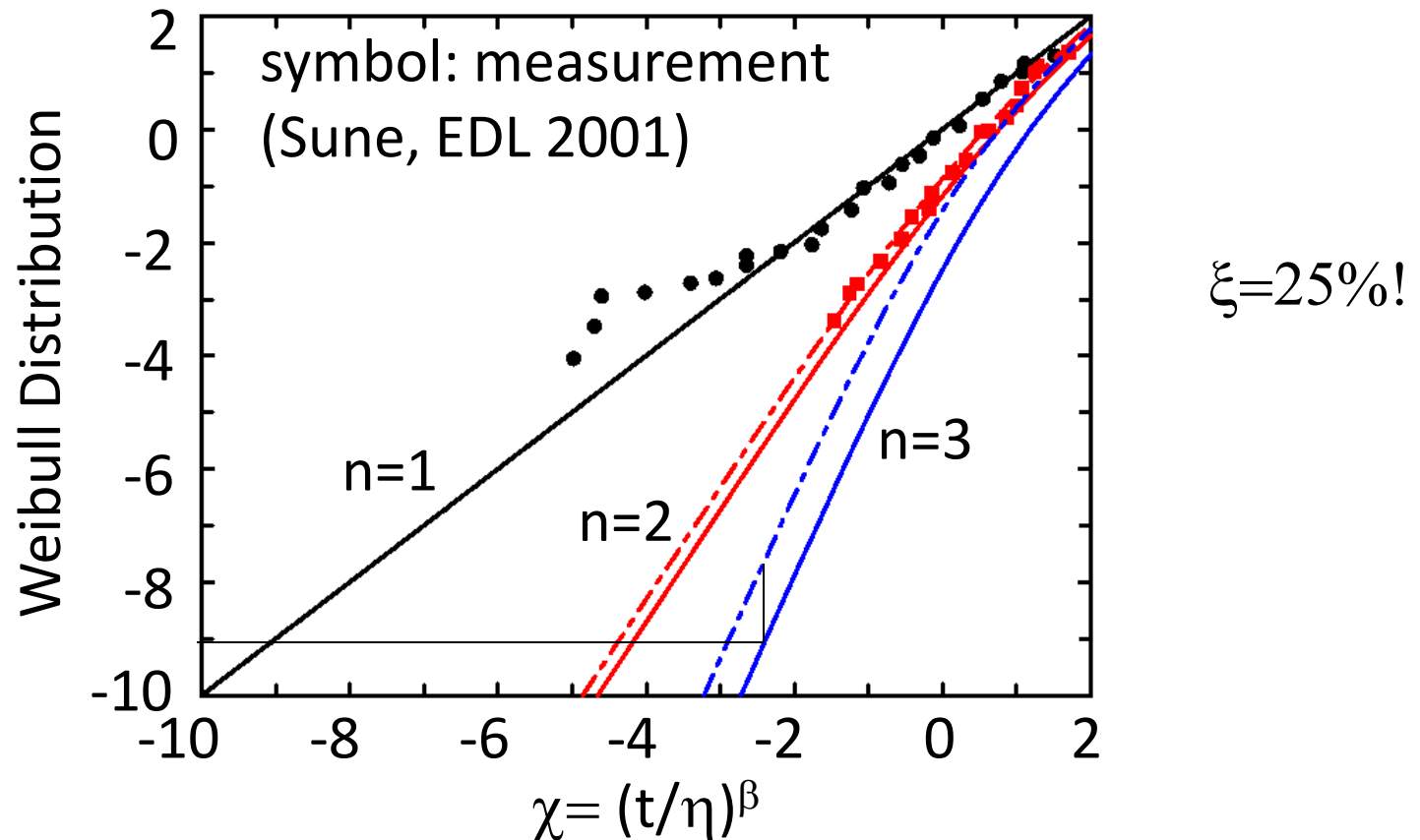
computing number of devices with n-SBD



Recall: Island-size distribution ...

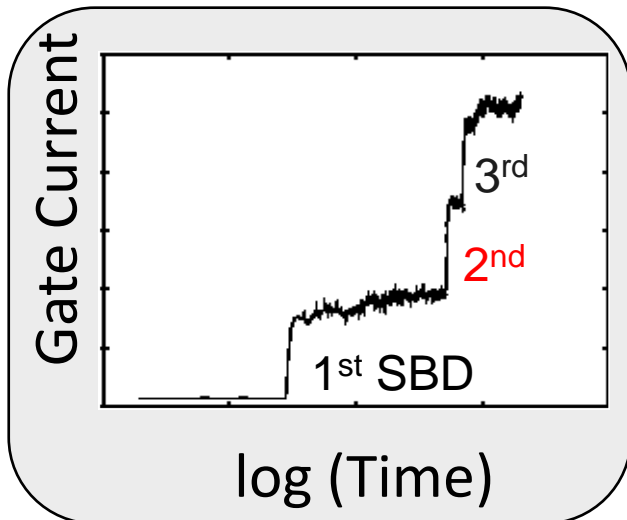
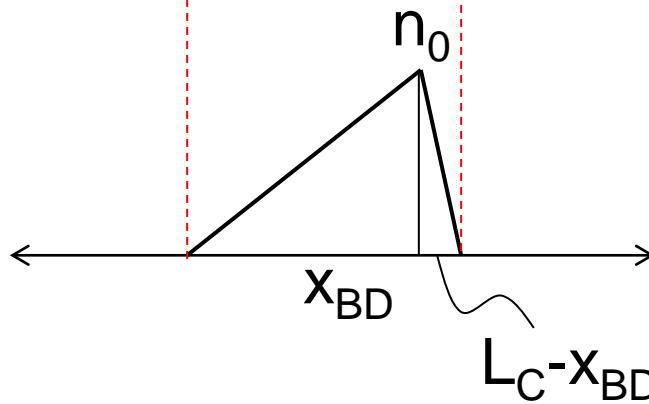
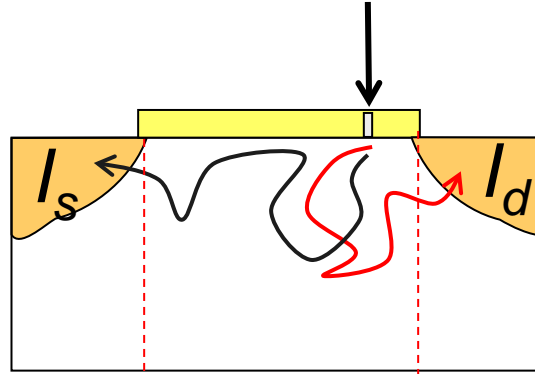
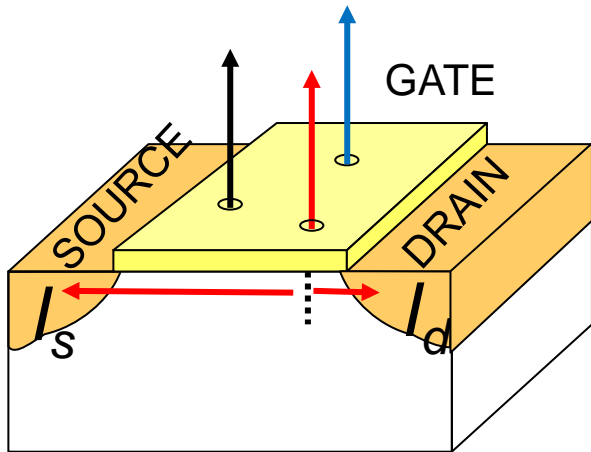
correlated distributions for multiple SBD

$$P_n = f(\xi) (\chi^n/n!) \exp(-\chi)$$



By measuring first and second SBD distributions, we determine ξ ; which allows computation of all other distributions

current ratio technique



$$J = qD \frac{dn}{dx} + n\mu E$$

$$\nabla \cdot J = 0$$

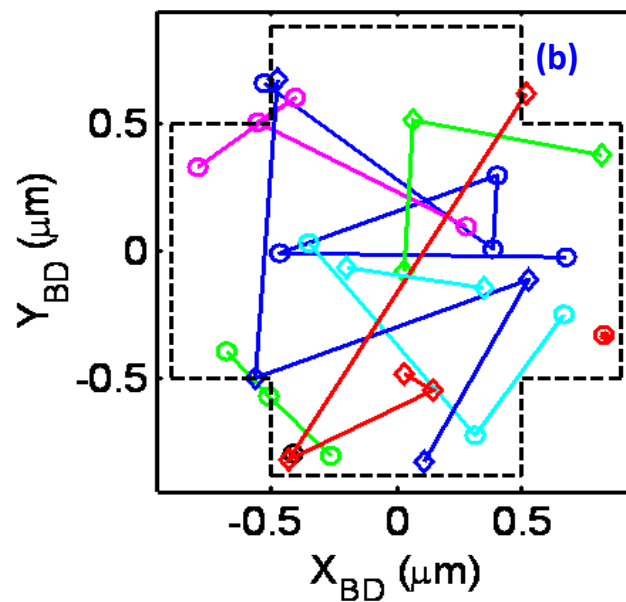
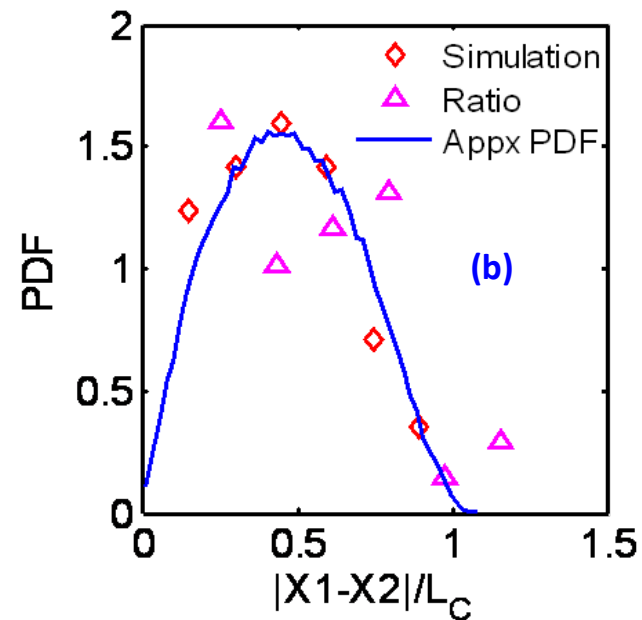
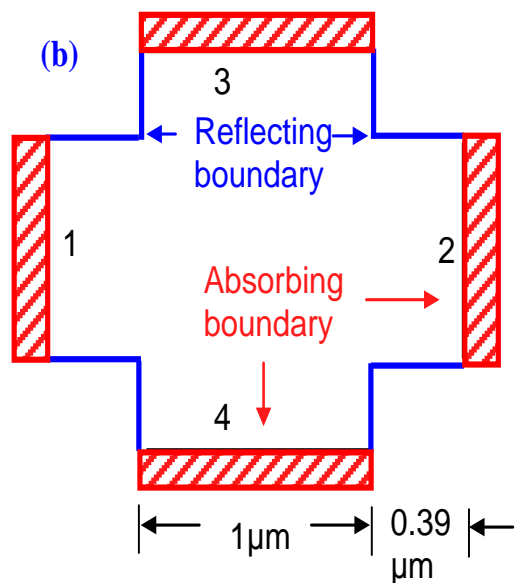
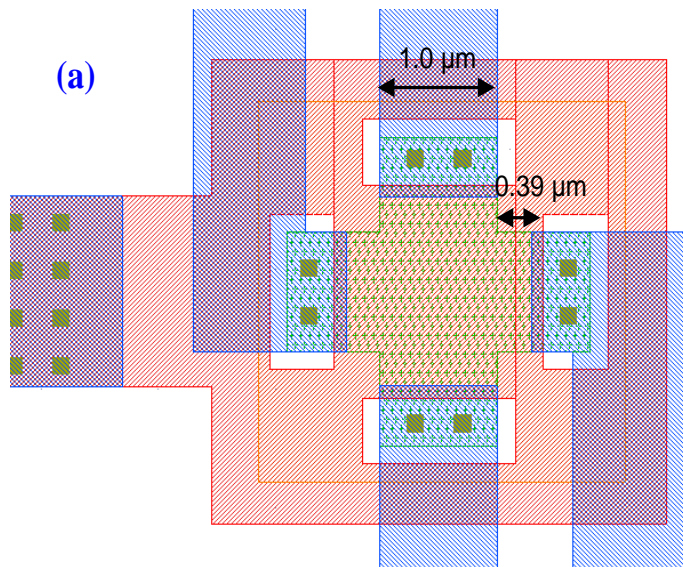
$$D \frac{d^2 n}{dx^2} = 0$$

$$n = Ax + B$$

$$J_s = qD \frac{n_0}{x_{BD}}$$

$$\frac{J_d}{J_s + J_d} = \frac{x_{BD}}{L_C}$$

spatially uncorrelated breakdown

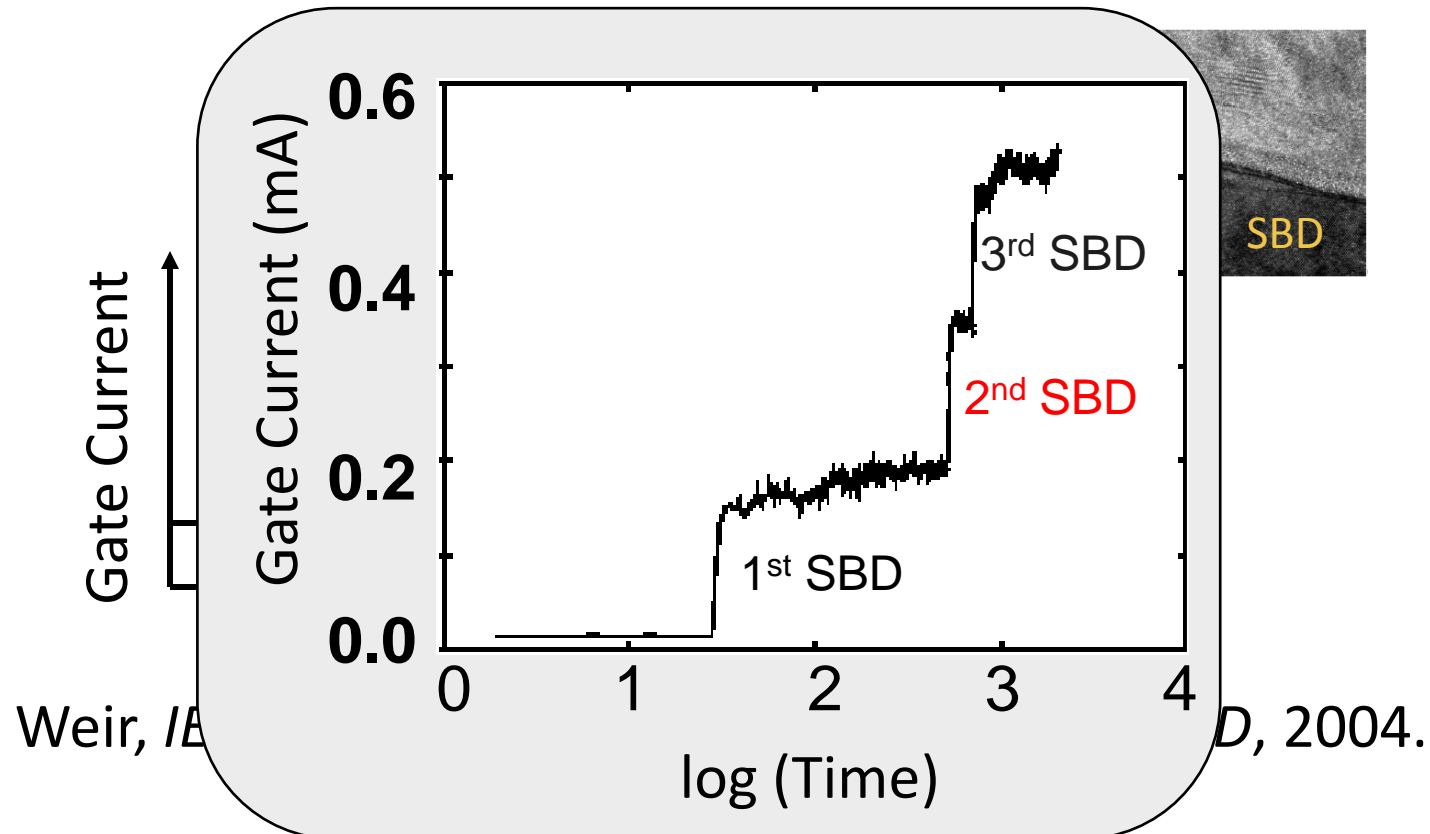
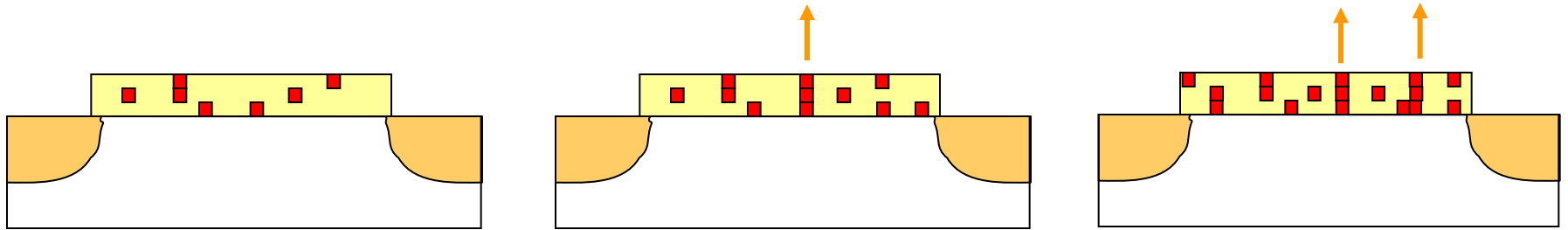


conclusions

- ➡ The reliability of modern ultrathin oxides involve delicate interplay between reduced defect generation at low voltages, statistics of failure distribution, and uncorrelated generation of breakdown paths.
- ➡ The reliability of ultra-thin gate dielectric is primarily dictated by 'hot' contacts – hence the difference between PMOS and NMOS reliability. The uncorrelated breakdown.
- ➡ The physics of statistical distribution of failure times and that of length scaling in very short channel transistors are the same, because they are based on similar physical principles.

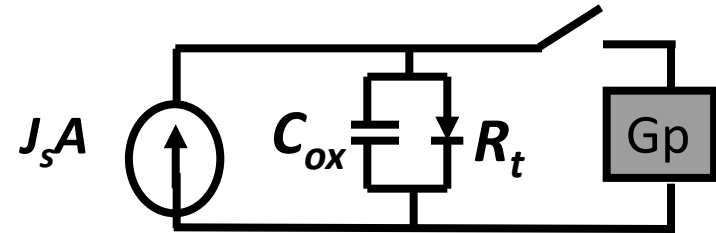
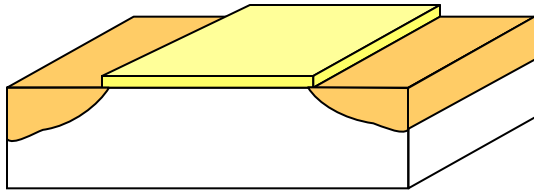
reference

soft breakdown for PMOS

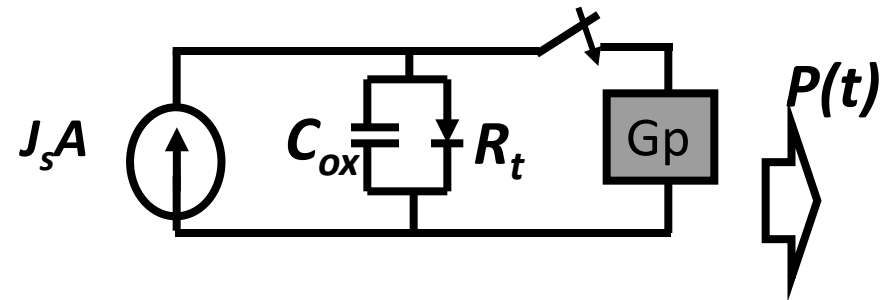
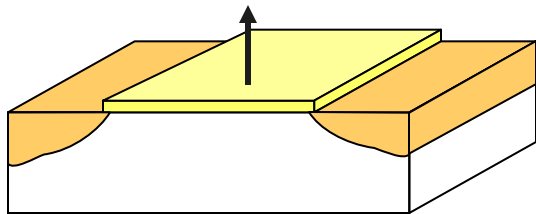


simple model for soft/hard breakdown

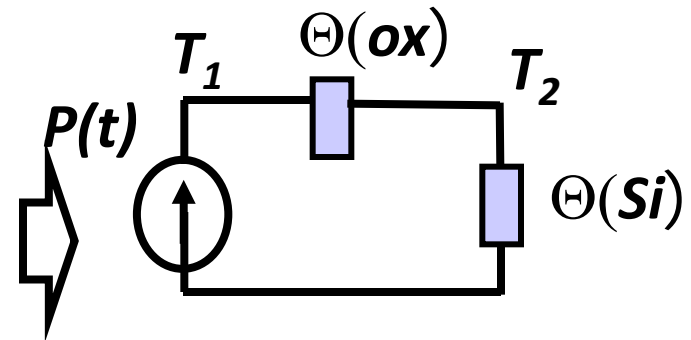
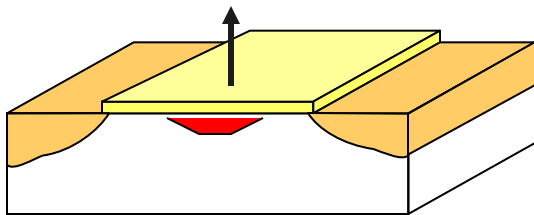
(a) $t < \text{TBD}$, only tunneling



(b) $t = \text{TBD}$, BD current initiates

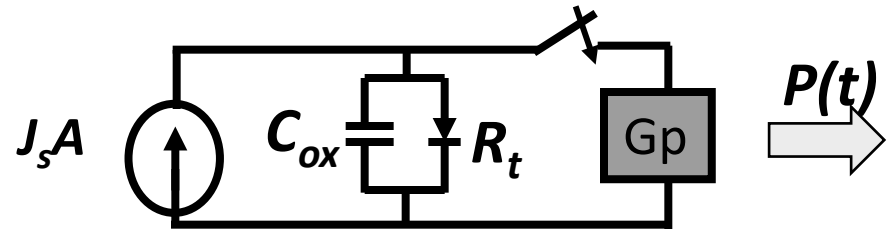
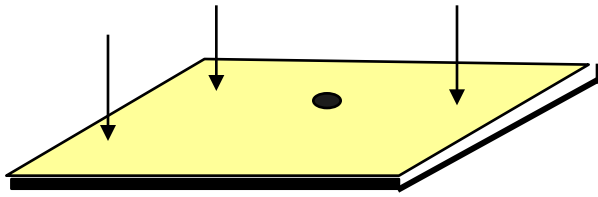


(c) $t > \text{TBD}$, transient heating

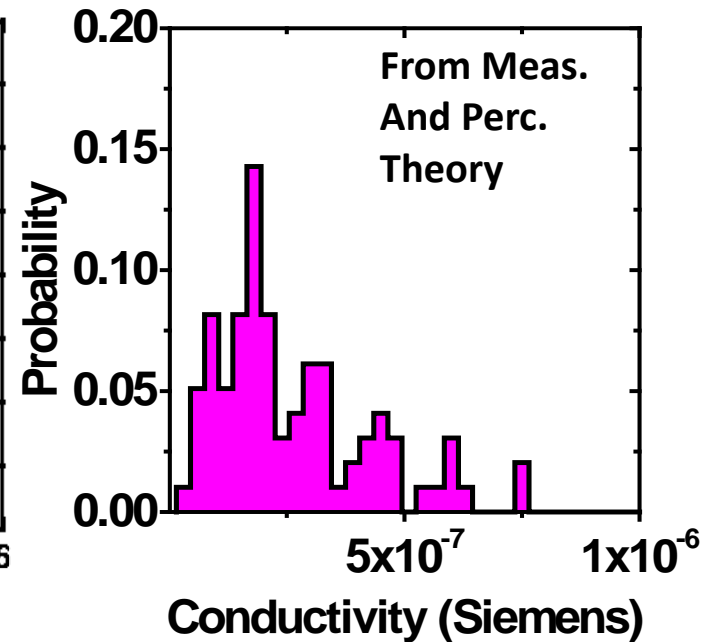
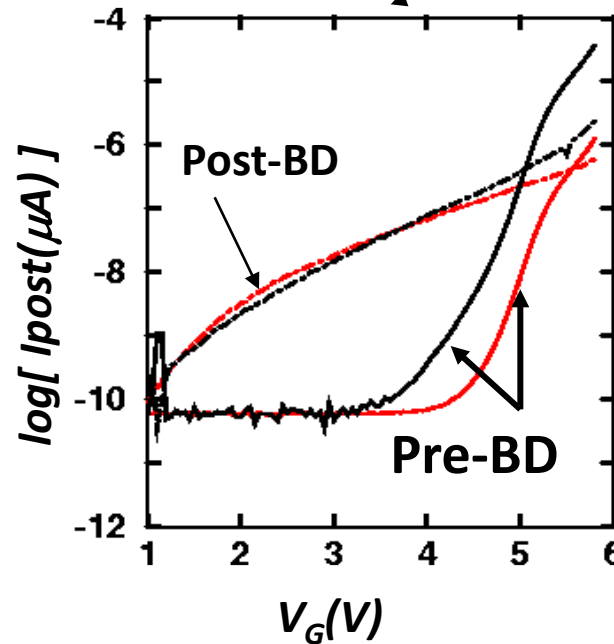
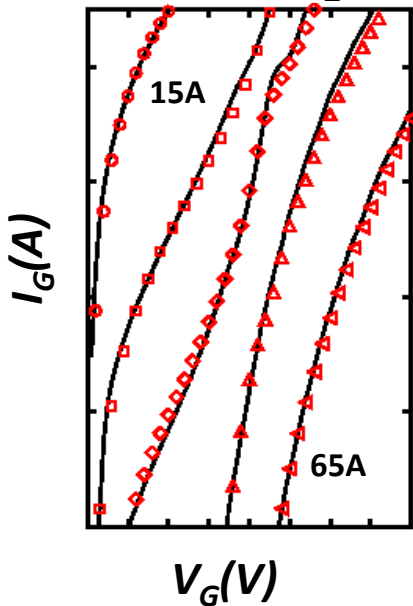


If $P(t)$ below certain threshold, breakdown will be soft

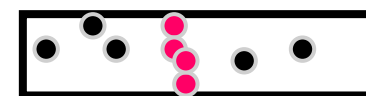
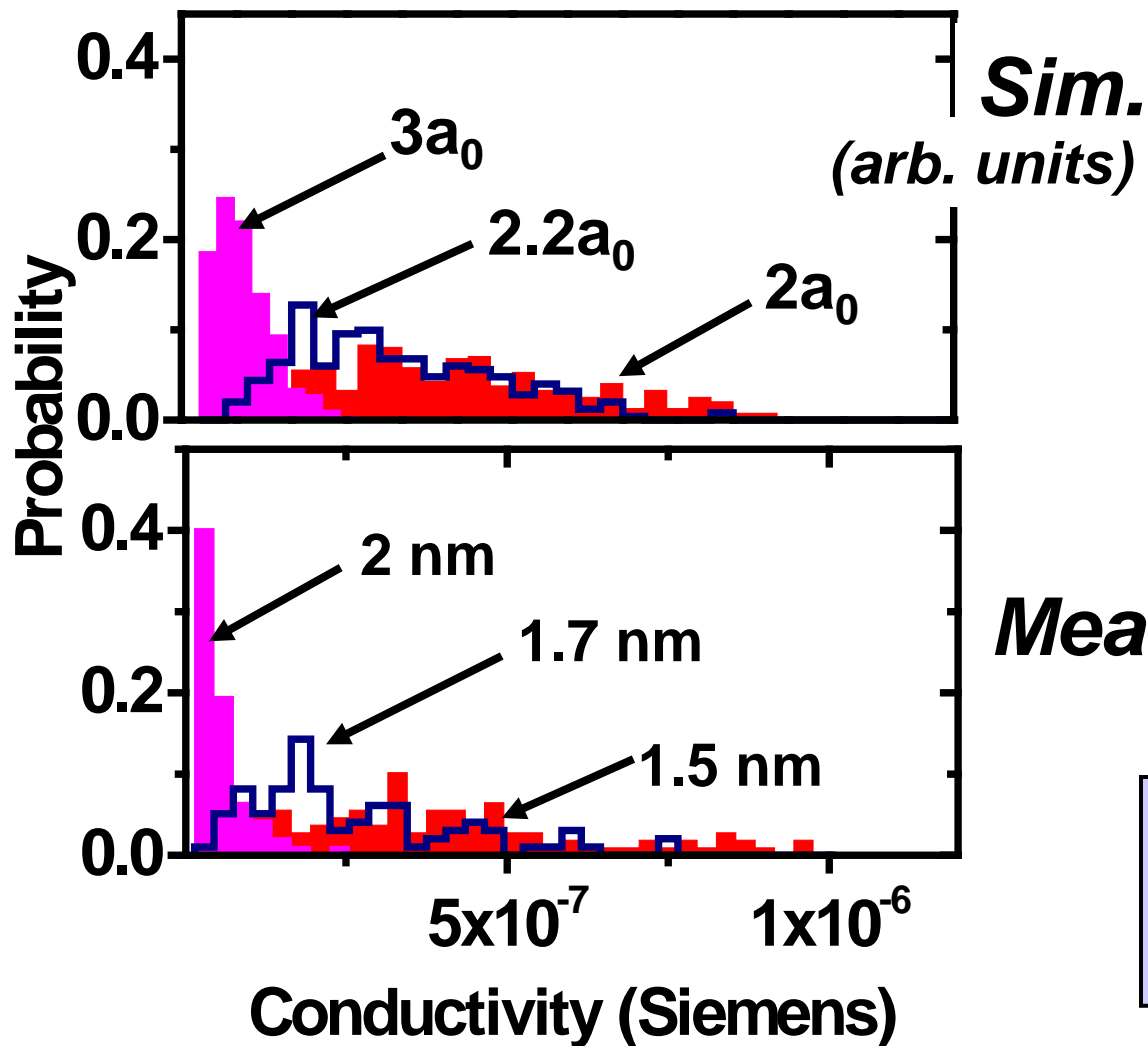
a simple model for SBD and HBD



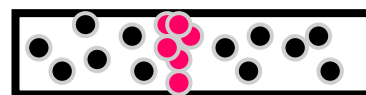
$$AC_{ox} (dV/dt) + A\alpha \exp(-\beta/V) + \{g_0\}V^\delta = AJ$$



statistical distribution of perc. resistance



Sample 1



Sample 2

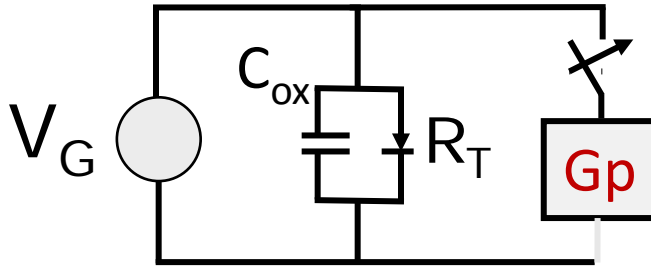


Sample n

Meas

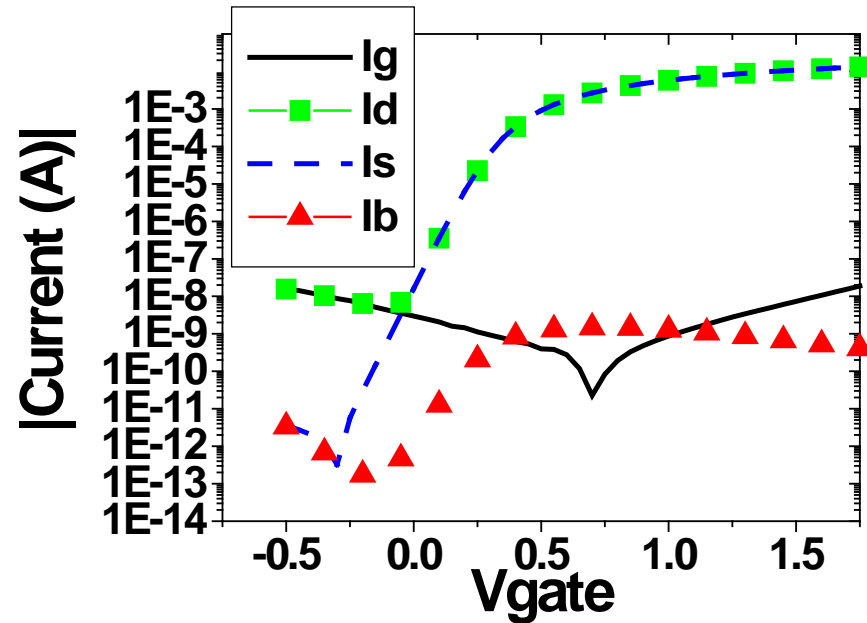
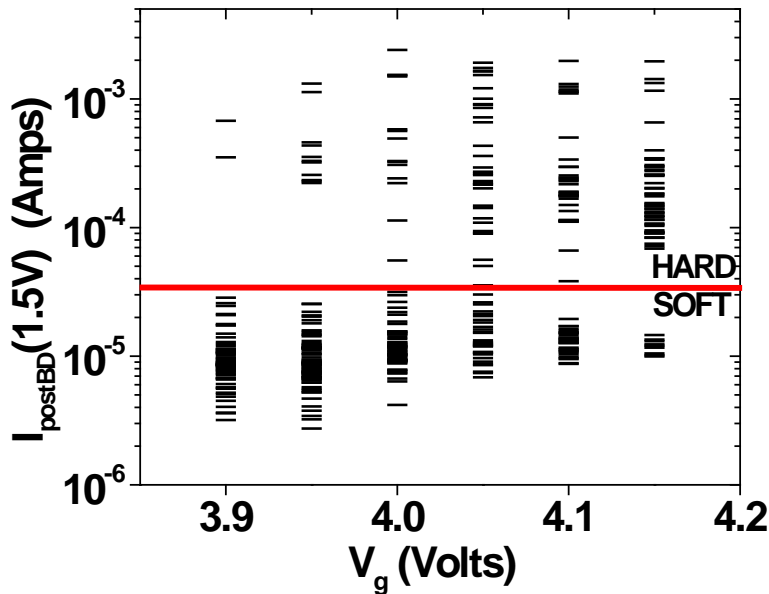
- Weakly thickness dependent
- $G_{\max}/G_{\min} = 5 - 10$

soft breakdown at reduced voltage



$$P = G_p V_G^2$$

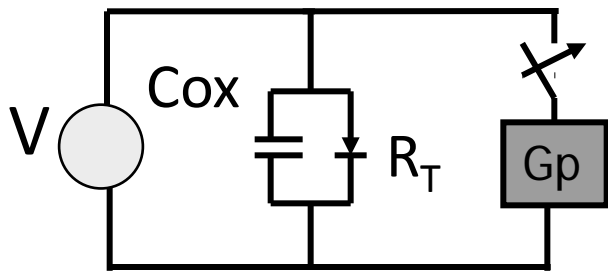
Softer BD ←



Expt. Evidence of SBD @ low V_G

Performance unaffected by SBD

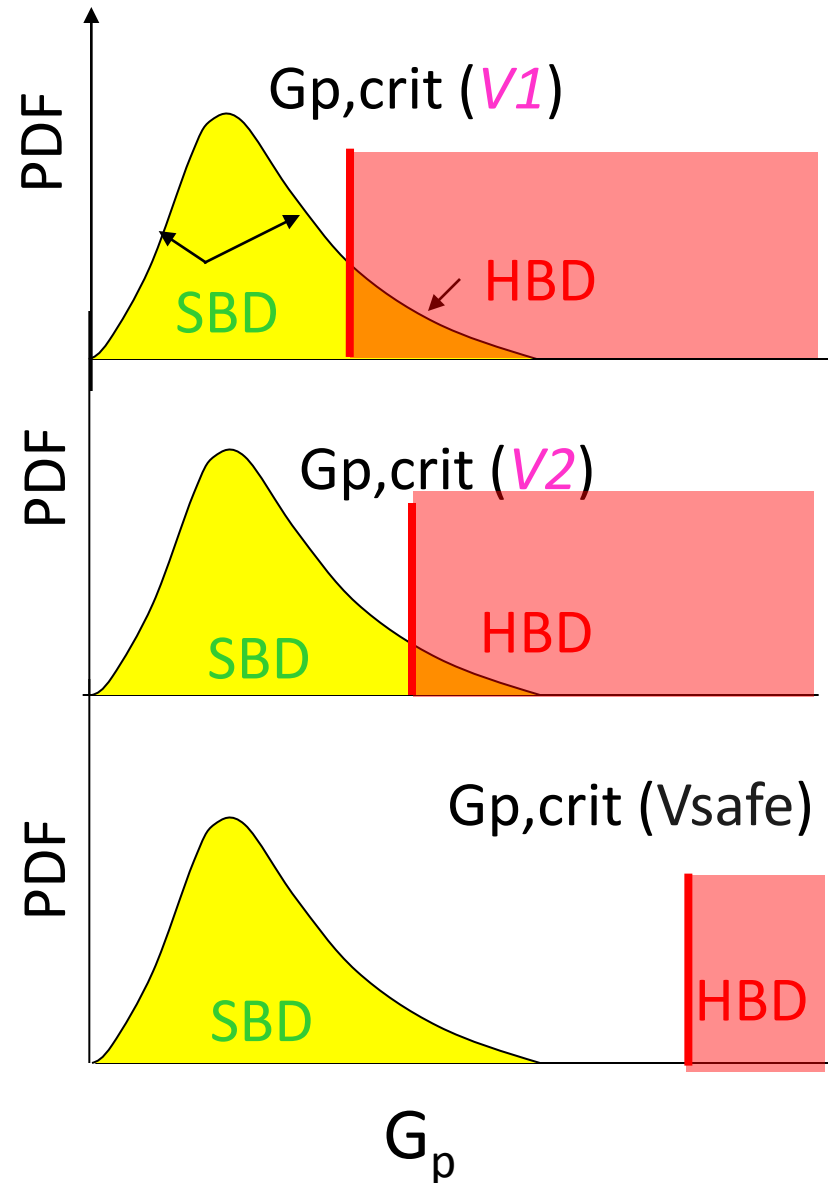
G_p is known, how to determine P_{THER} ?



$$P = G_p V^2$$

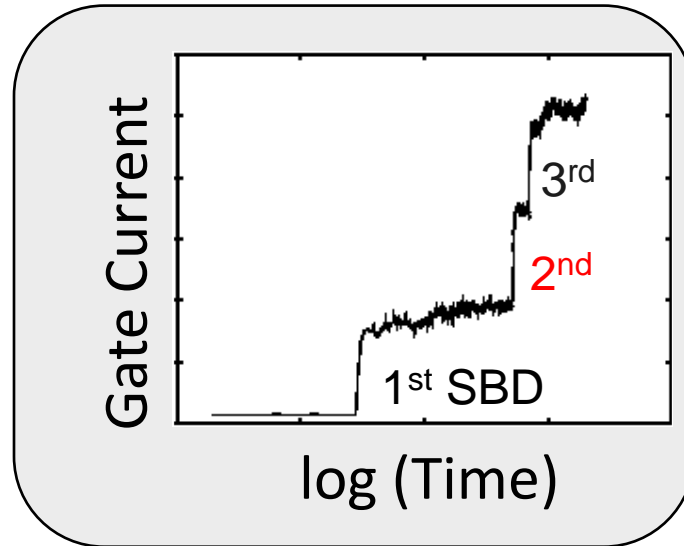
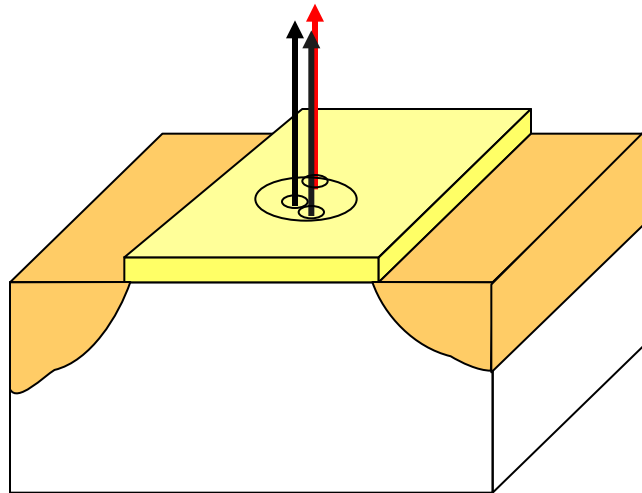
$$G_{pcrit} = P_{THER} / V^2$$

Based on ratio of soft to hard- BDs at V_1 and V_2 , determine P_{THER} .
Use it can determine V_{safe} .

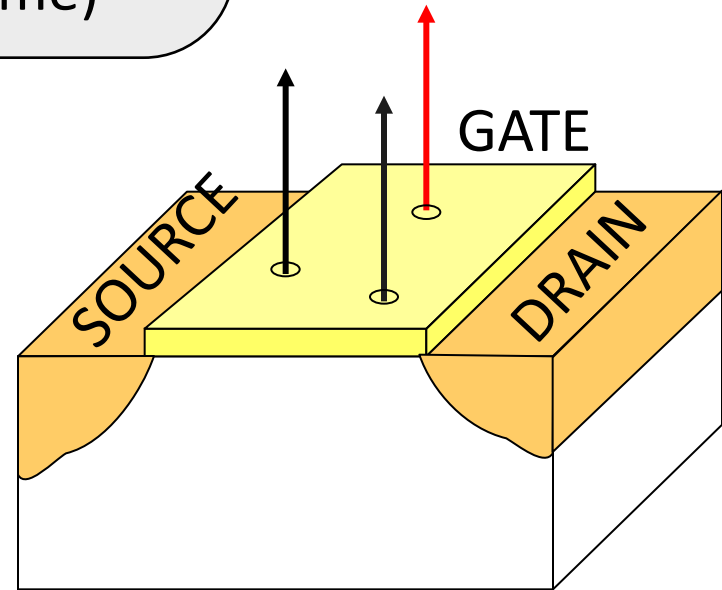


features of hard and soft breakdown

Hard
Breakdown

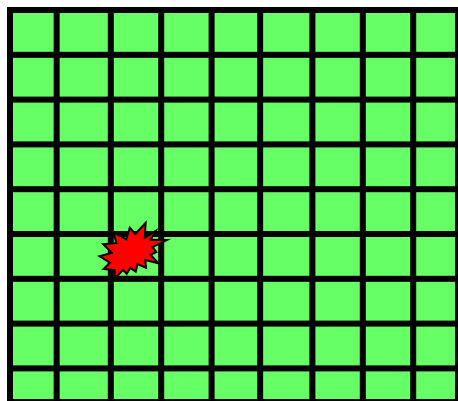


Soft
Breakdown

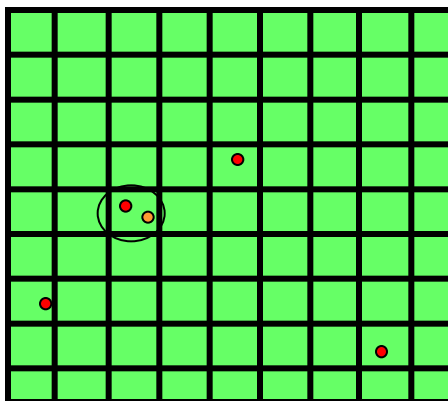


theory of correlated soft breakdown

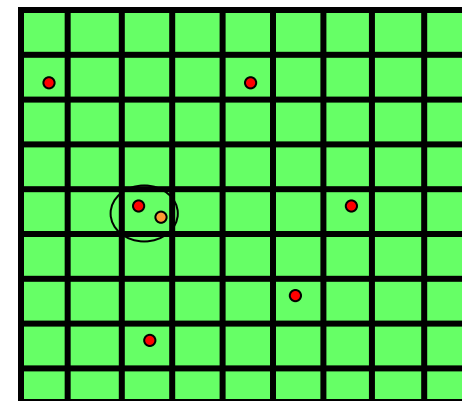
Std. definition



Measurement



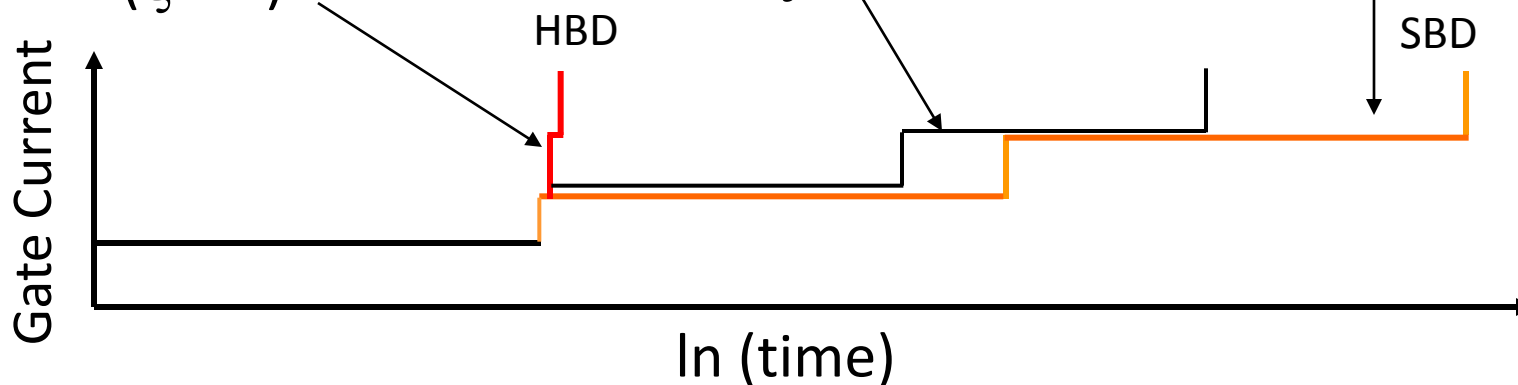
Theory



Completely correlated
($\xi = \infty$)

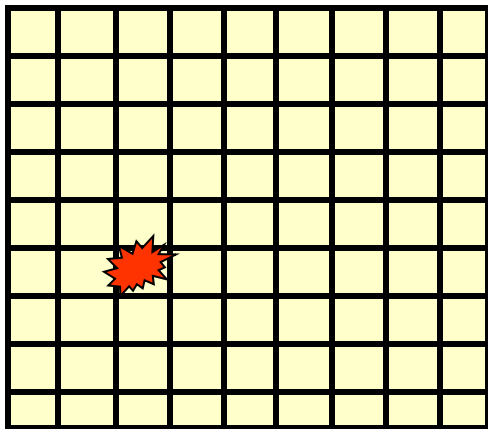
“Essentially” uncorrelated
($\infty < \xi < 0$)

Completely uncorrelated
($\xi = 0$)

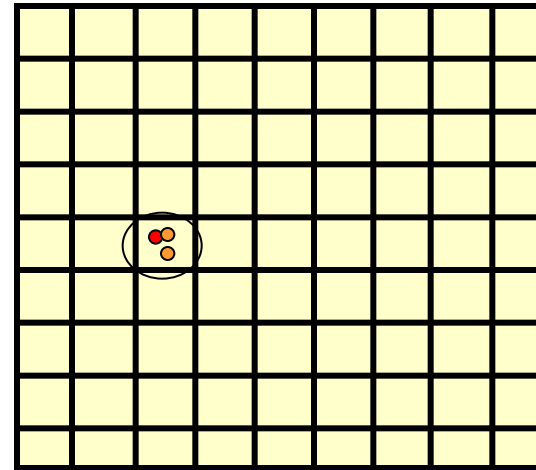


physical reasons for improved reliability

Std. reliability definition

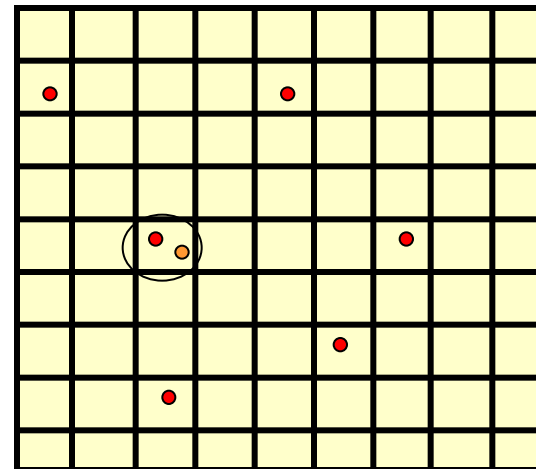
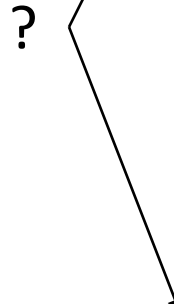


new reliability definition



Correlated

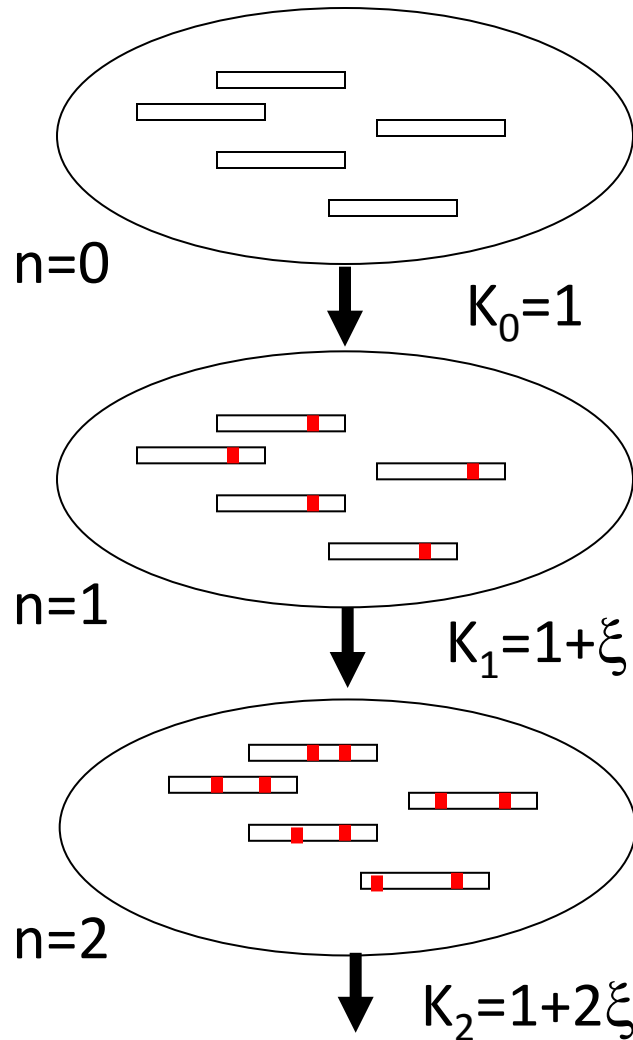
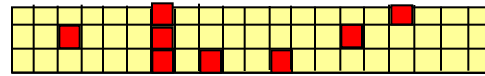
Few BD in IC
before 2nd BD in
the same
transistor



Uncorrelated

Many BD in IC
before 2nd BD in
the same
transistor

computing number of devices with n-SBD



$$\frac{dP_o}{d\chi} = -k_o P_o$$

$$\chi = (t/\eta)^\beta$$

$$\frac{dP_n}{d\chi} = k_{n-1} P_{n-1} - k_n P_n$$

$$P_o = \exp(-\chi)$$

$$P_n = f(\xi) \left(\frac{\chi^n}{n!} \right) \exp(-\chi)$$

$$f(\xi) = \prod_{m=0}^{n-1} (1+m\xi) [1 - \exp(-\xi\chi)] / \xi\chi^n$$